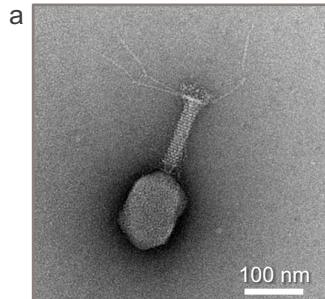




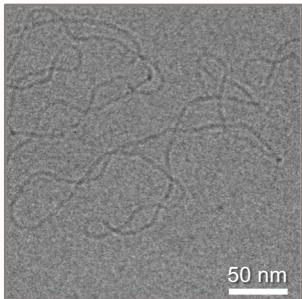
Transmission Electron Microscopy (TEM)

CCMX Summer School 2023

Biology and life science

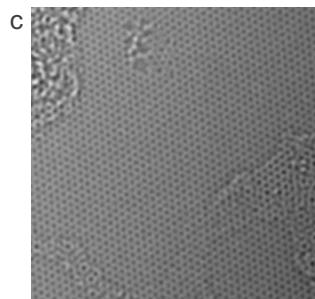


T4 virus ^a
A bacteriophage that infects Escherichia coli bacteria

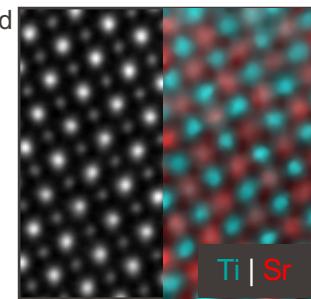


DNA molecule ^a

Chemistry & materials research

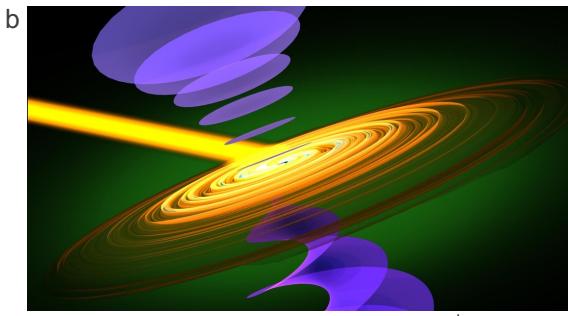


Imaging and spectroscopy at atomic resolution ^{c,d}

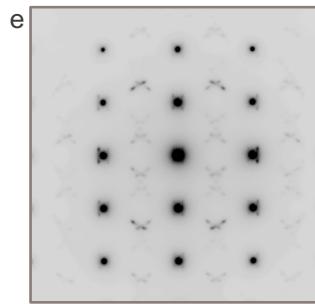


Ti | Sr

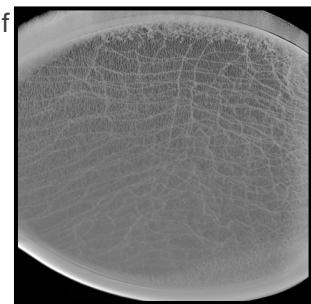
Fundamental physics



Ultrafast electron vortex beams ^b



Crystallographic studies ^e



Analyzing crystal defects ^f

Introduction to transmission electron microscopy (TEM)

TEM imaging and diffraction

High-resolution TEM

Scanning TEM (STEM)

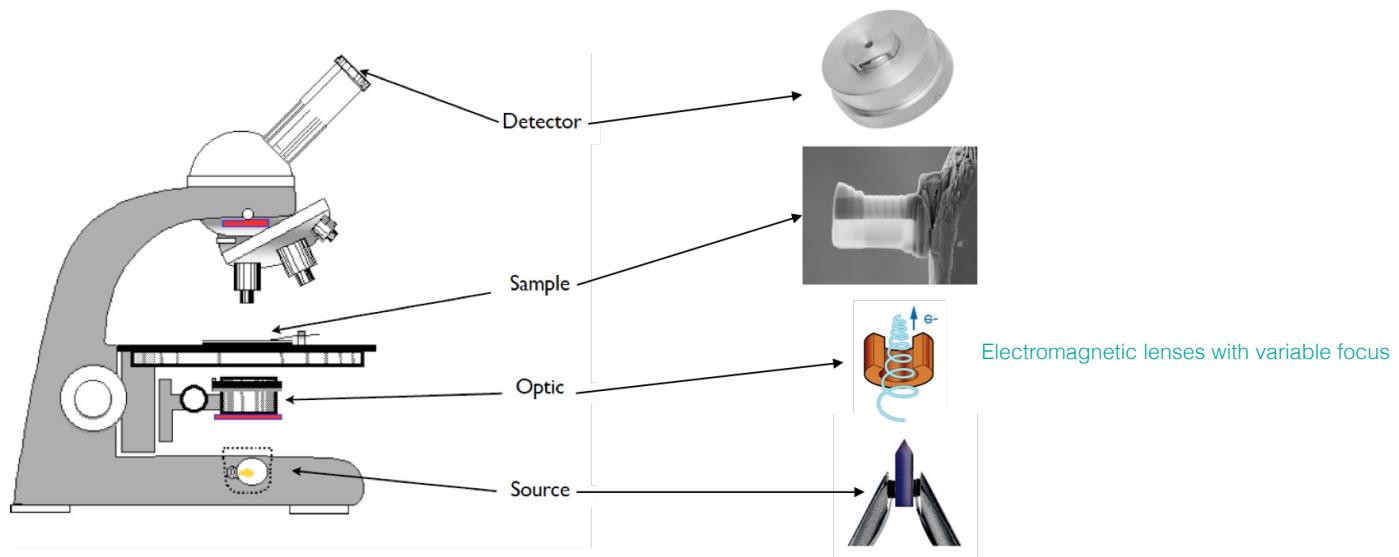
Energy-dispersive X-ray (EDX) analysis in STEM

Electron energy-loss spectroscopy (EELS)

In situ TEM

Summary

Introduction to TEM



Visible light

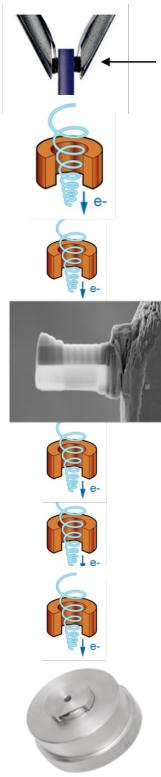
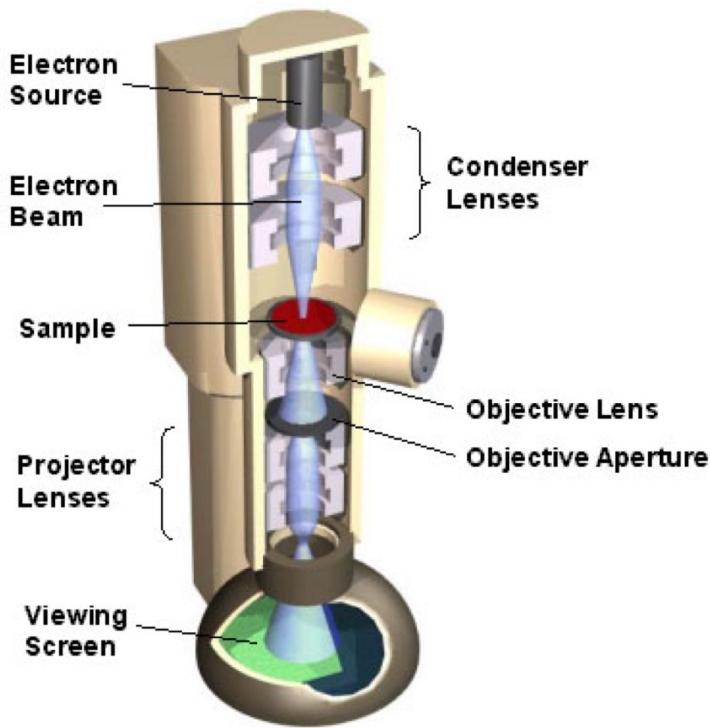


Fast electrons
100–300 keV
(0.5 – $0.8 c$!)

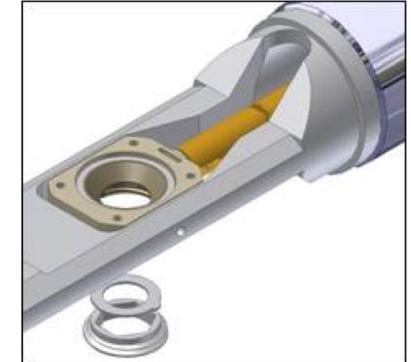
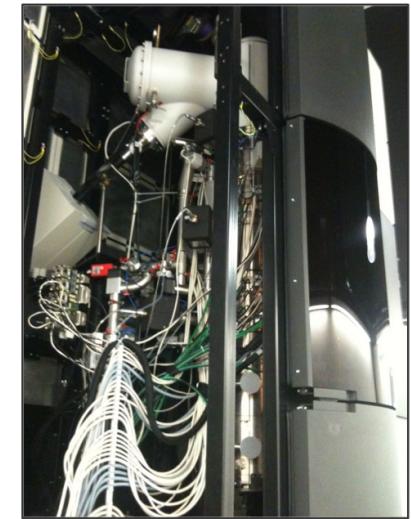
Wave-particle duality

■ Can consider analogous to projection light microscopy, but with better resolution

Introduction to TEM



Double Cs-corrected FEI Titan-Themis @ CIME-EPFL

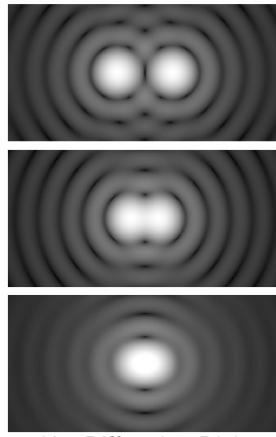


Specimen should be electron transparent:
several nanometers thick

Why fast electrons?

The resolution of an optical microscope is defined as the minimum distance between two point sources (e.g. objects) such that their presence can be distinguished in the image.

Abbe's definition of maximum resolution of an optical system states that the smallest feature resolved is limited by diffraction.



Airy Diffraction Disks

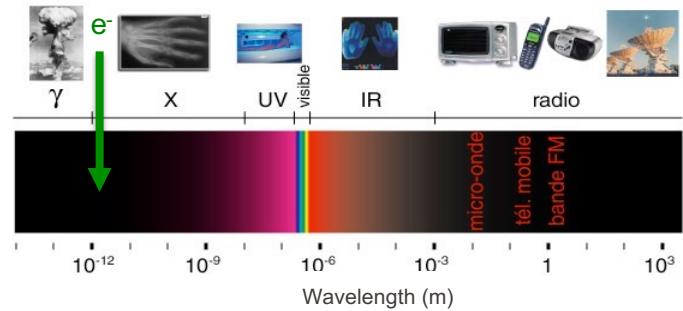
Visible light: $\lambda \approx 300\text{-}700\text{ nm}$ → resolution around half of the λ

Electrons: $\lambda = h \cdot c / E$: Wave-particle duality

@ 200 keV: $\lambda = 0.025\text{ \AA}$ << interatomic spacing*

$$r = \frac{1.22\lambda}{2 \sin \theta} \approx \frac{0.61\lambda}{\theta}$$

For the 200 keV TEM around $< 1\text{ \AA}$ resolution possible



Why fast electrons?

	Advantageous	Disadvantageous
Visible light	Not very damaging Easily focused Eye detector	Long wavelengths (400 nm)
X-rays	Small wavelength (Angstrom) Good penetration	Hard to focus Damage sample
Neutrons	Low sample damage Small wavelength (pm)	How to produce? How to focus?
Electrons	Small wavelength (pm) Can be focused to a sub-Å size probe Wave-particle duality	Damage sample Poor penetration (< x00 nm)

High energy electrons have a short wavelength

Easy to produce high brightness electron beams

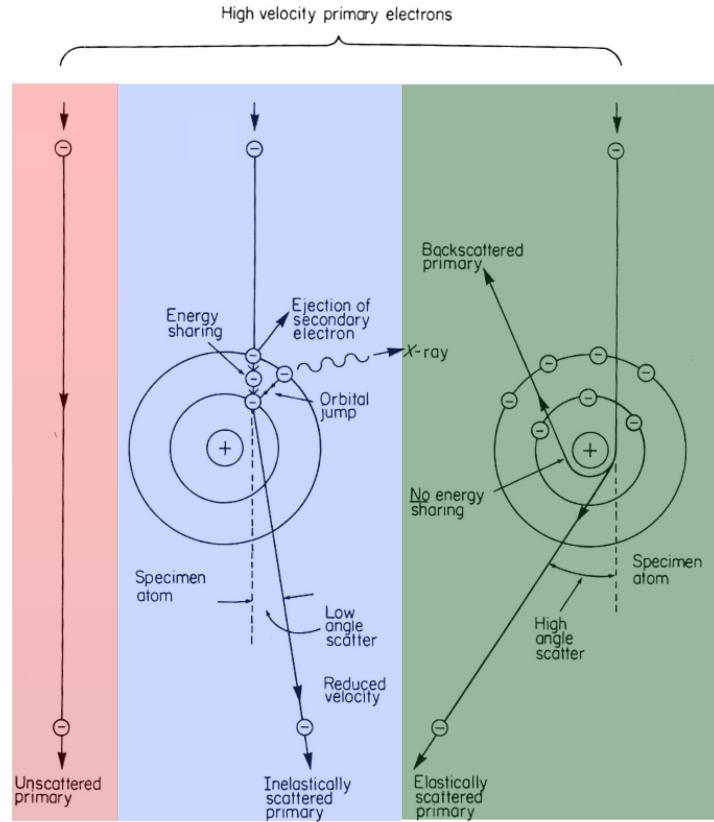
Easy to manipulate: focused

Interact strongly with matter

Electron microscopes are used not only for obtaining good resolution images but also:

- can be used as a diffractometer (TEM and EBSD)
- for chemical analyses (SEM and TEM)
- for imaging/measuring strain field in the sample (SEM and TEM)
- etc.

e- matter interactions



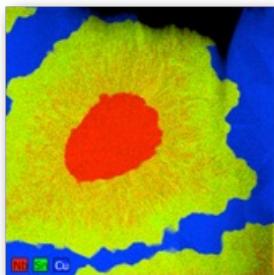
Inelastic events: The result is a **transfer of beam energy** to the specimen atom (**energy loss**) and a potential expulsion of an electron from that atom as a **secondary electron (SE)**.

If the vacancy due to the creation of a secondary electron is filled from a higher level orbital, an X-Ray or Auger characteristic of that energy transition is produced.

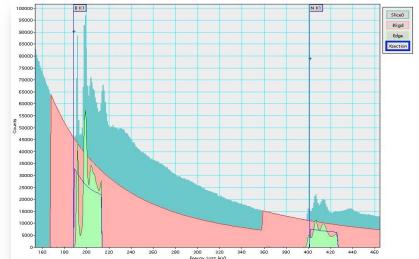


That's why TEMs are shielded!

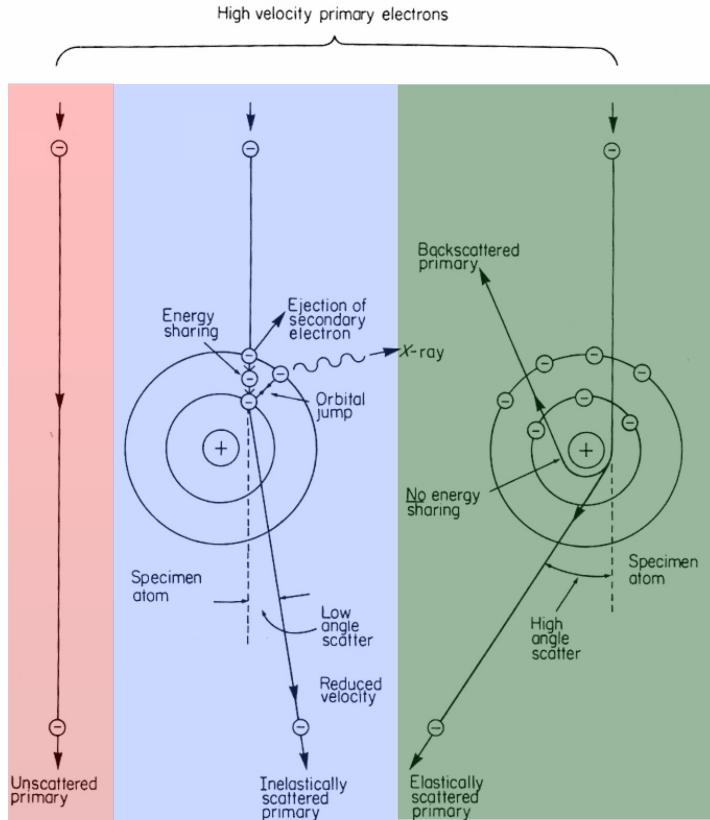
Characteristic X-rays



Electron energy-loss spectrum



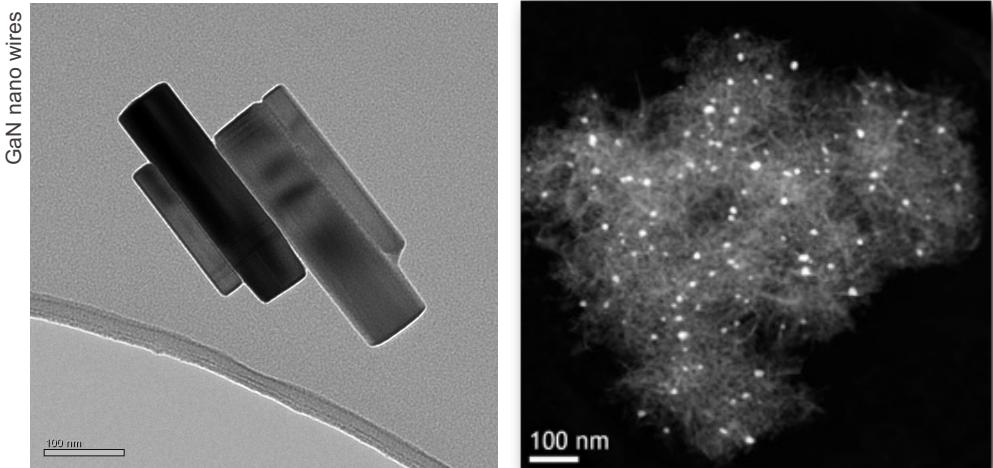
e- matter interactions



Elastic events occur when a beam electron interacts with the electric field of the nucleus or electron cloud of a specimen atom (Coulomb forces), resulting in a change in the direction of the beam electron **without a significant change in the energy** of the beam electron (< 1 eV).

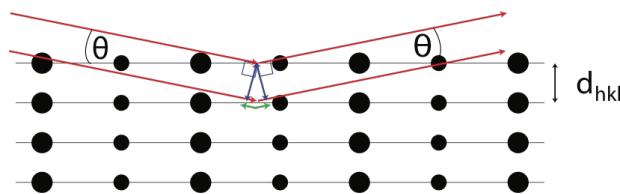
Coulombic interaction within the electron cloud, Low-angle scattering
Coulombic attraction by the nucleus, Higher-angle scattering

Thicker specimen or larger nucleus → More scattering



e⁻ as wave & Bragg scattering

For X-ray diffractometer



X-ray scattering:

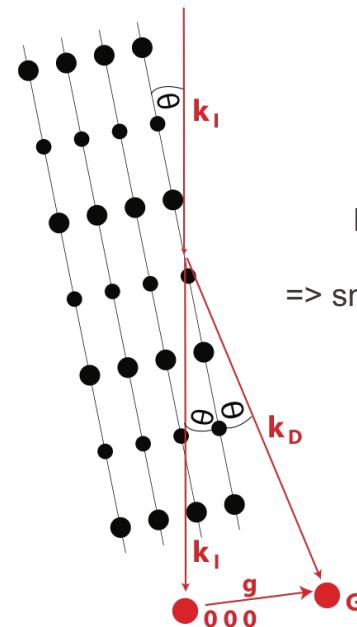
Path difference between reflection from planes distance d_{hkl} apart
 $= 2d_{hkl} \sin\theta$

=> Bragg law:
 $n\lambda = 2d_{hkl} \sin\theta$

or

$\lambda = 2d_{nhnknl} \sin\theta$

For TEM electrons come from top, but otherwise geometrically the same



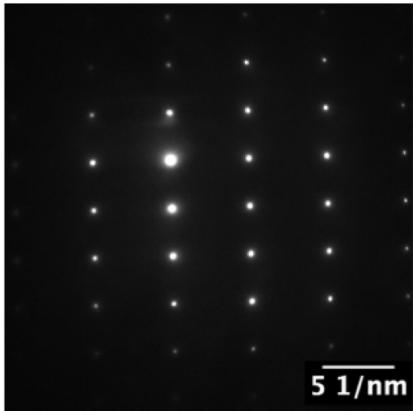
Electron diffraction: $\lambda \sim 0.001$ nm
 therefore: $\lambda \ll d_{hkl}$

=> small angle approximation: $\lambda \approx 2d_{nhnknl} \sin\theta$

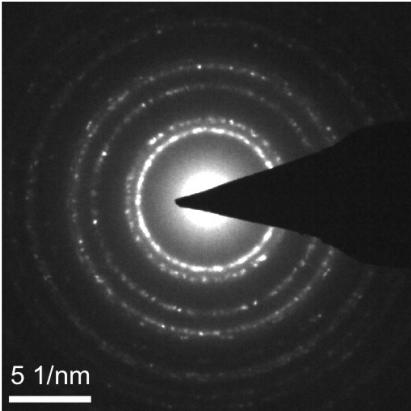
=> Bragg diffraction at angle 2θ

e⁻ as wave & Bragg scattering

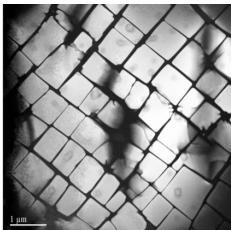
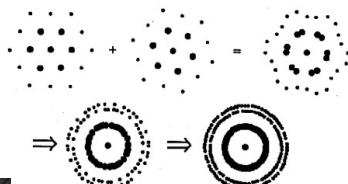
Electron diffraction pattern



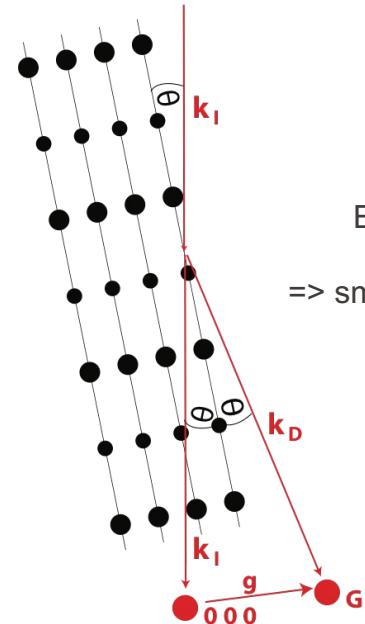
Spot pattern from a single crystal
Spots represent different (hkl) planes



Ring pattern as many crystallites oriented
differently in diffraction conditions



Therefore TEM gives image & diffraction!



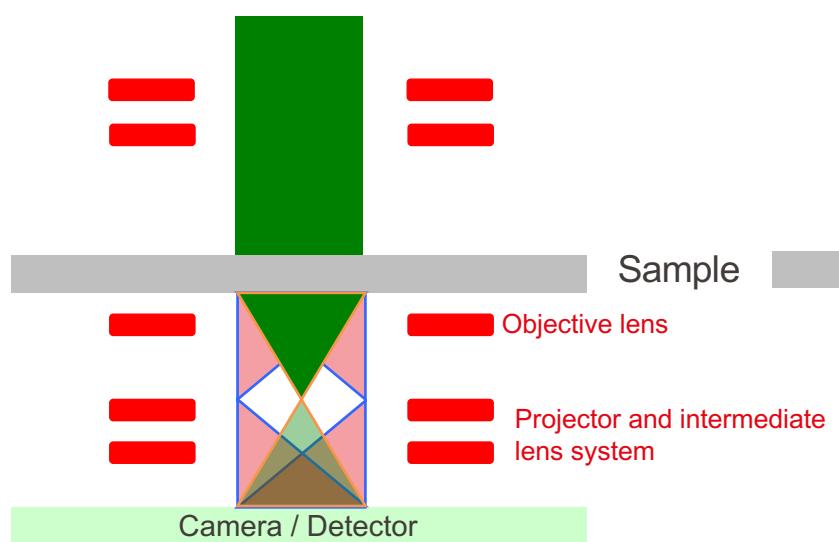
Electron diffraction: $\lambda \sim 0.001 \text{ nm}$
therefore: $\lambda \ll d_{hkl}$

=> small angle approximation: $\lambda \approx 2d_{hkhkn}\theta$

=> Bragg diffraction at angle 2θ

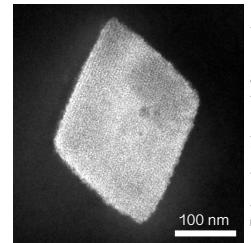
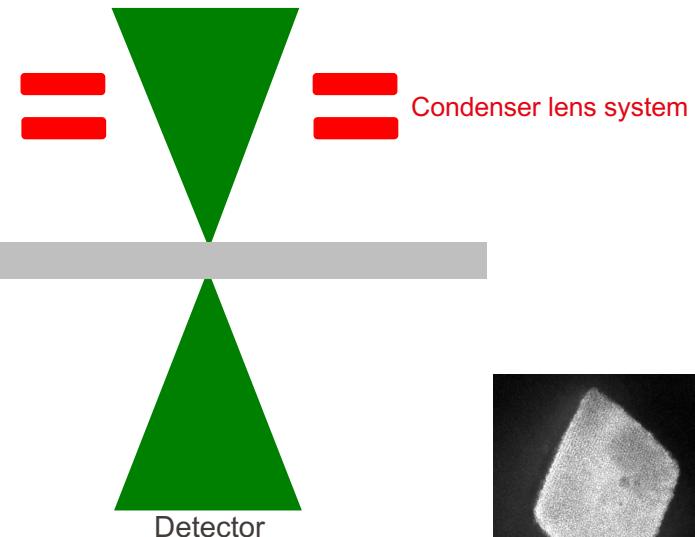
TEM operation modes

Conventional TEM

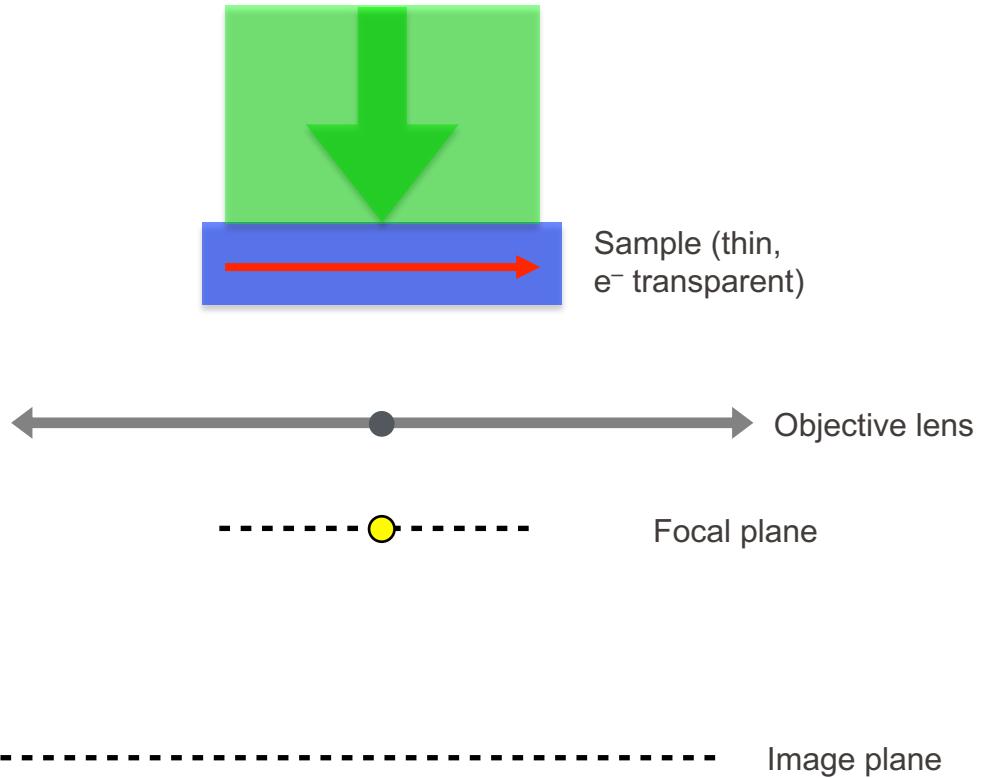


Scanning mode (STEM)

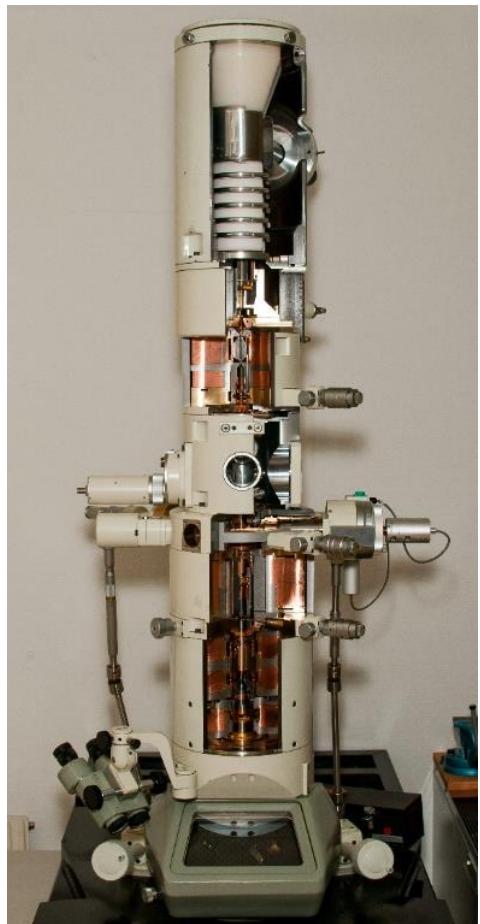
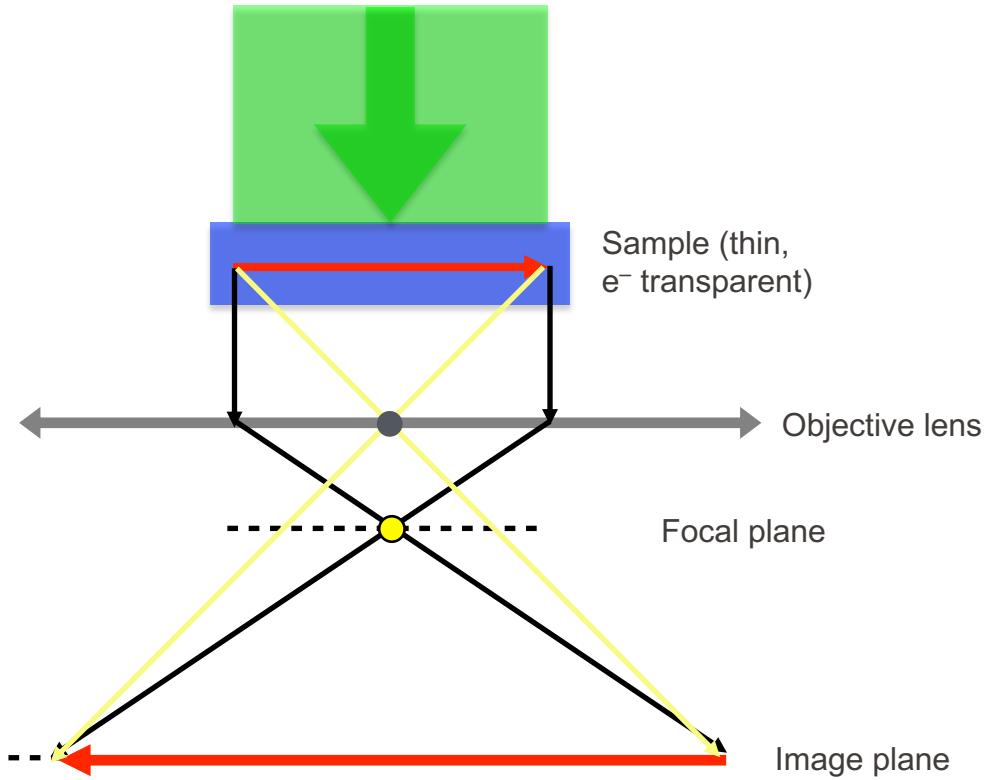
Electron beam (30-300 keV)



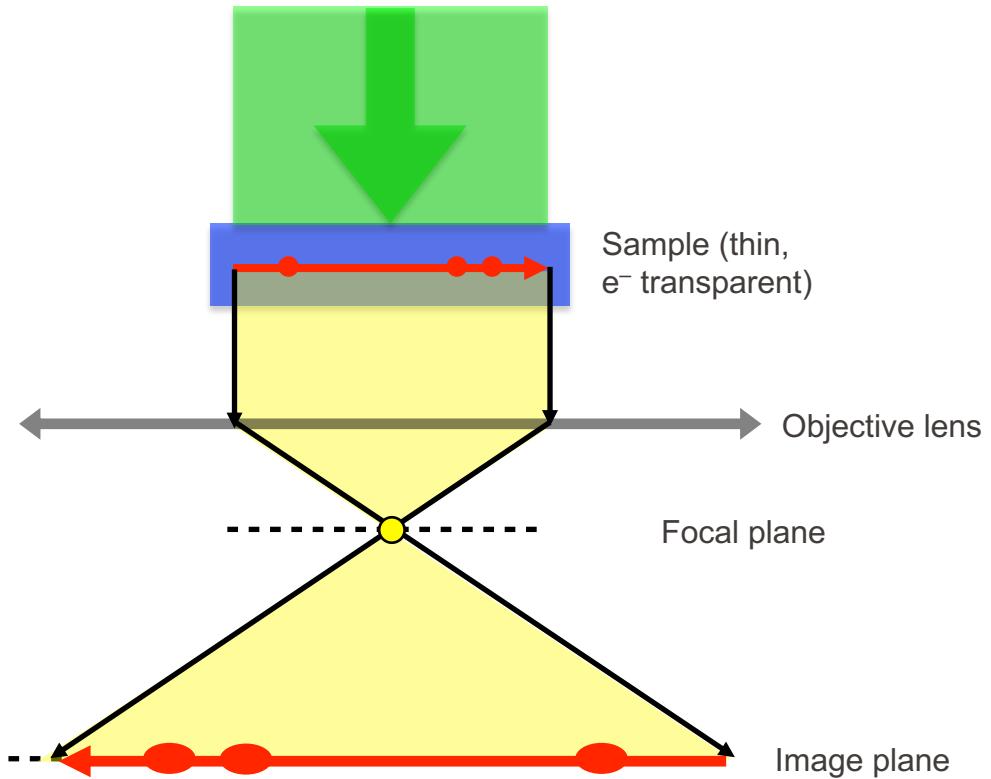
Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$



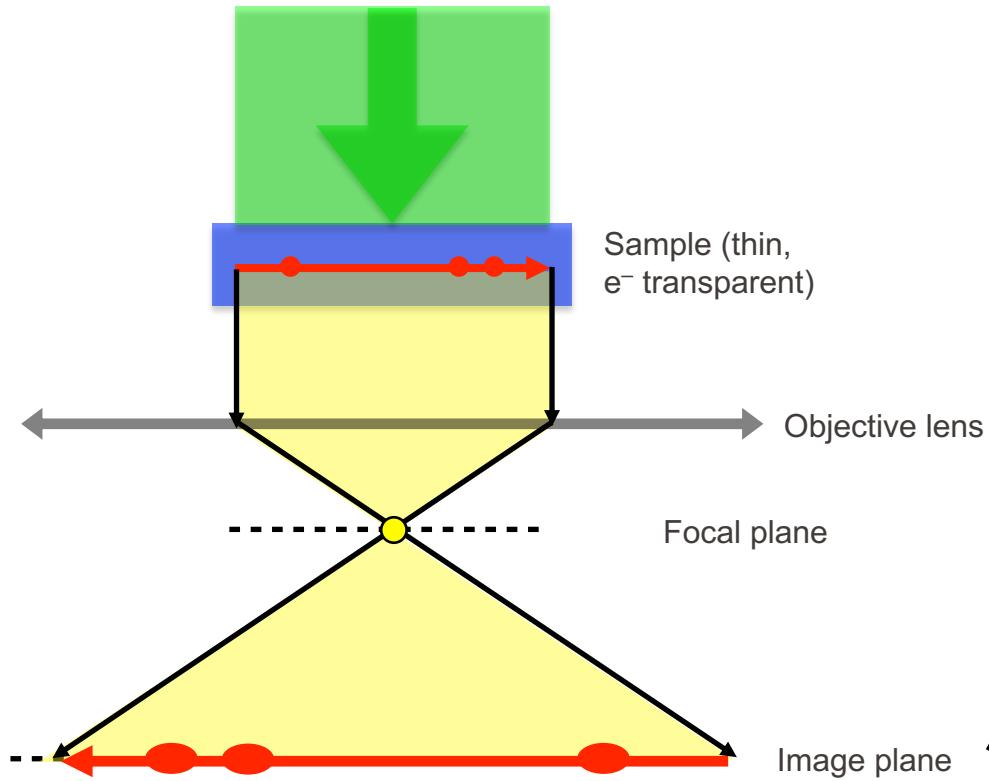
Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$



Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$

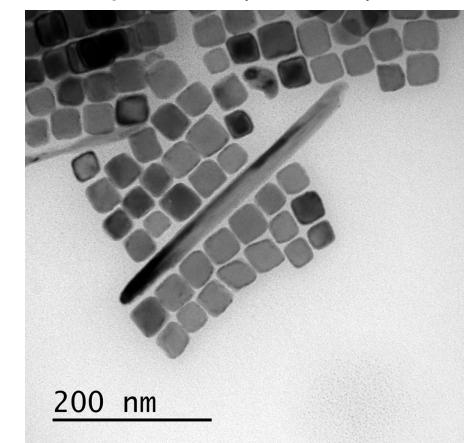


Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$



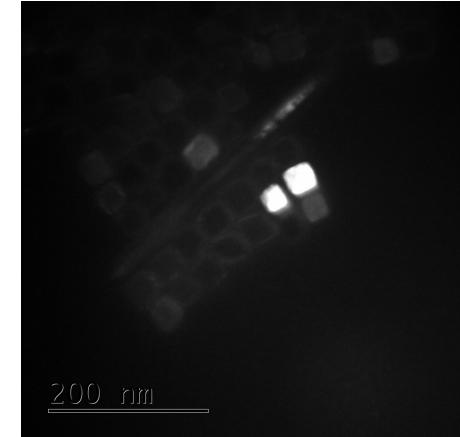
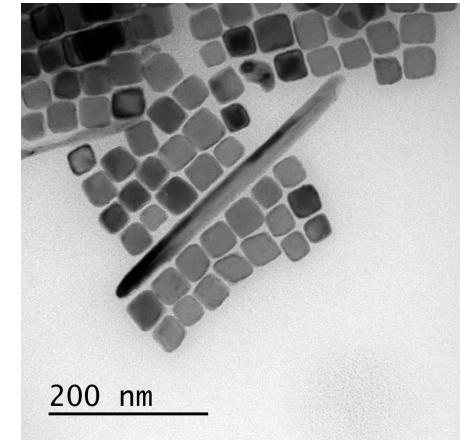
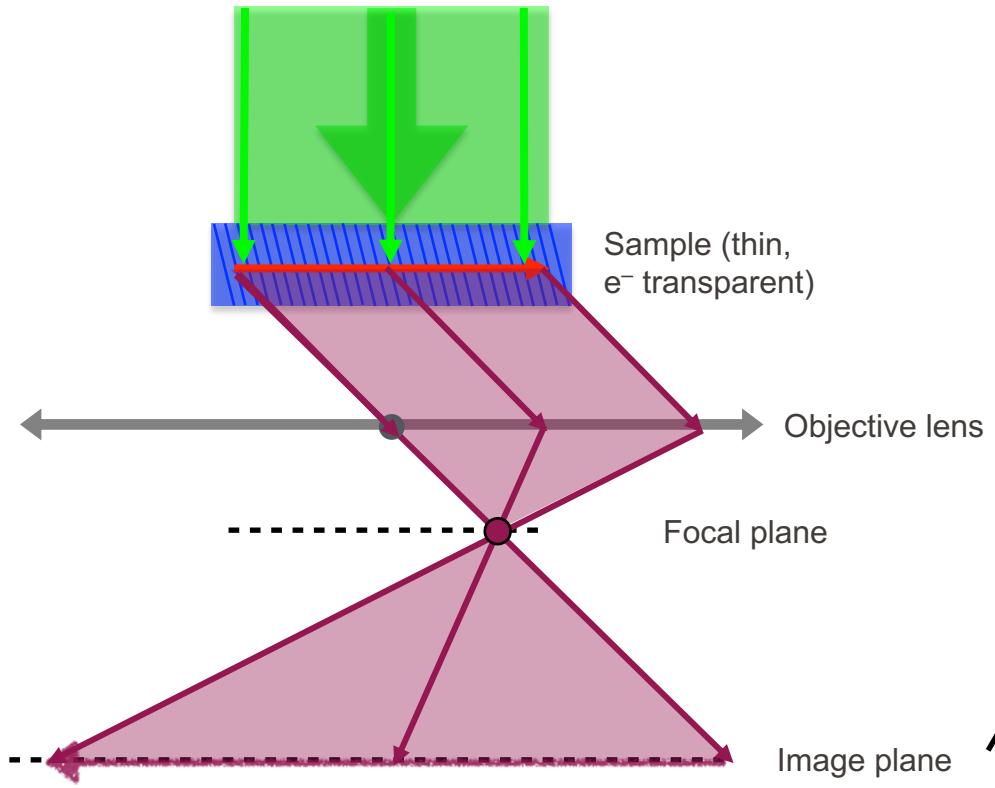
Why some cubic particles appear darker than others?

Cubic particles ($\approx 40 \text{ nm}$) of Cu

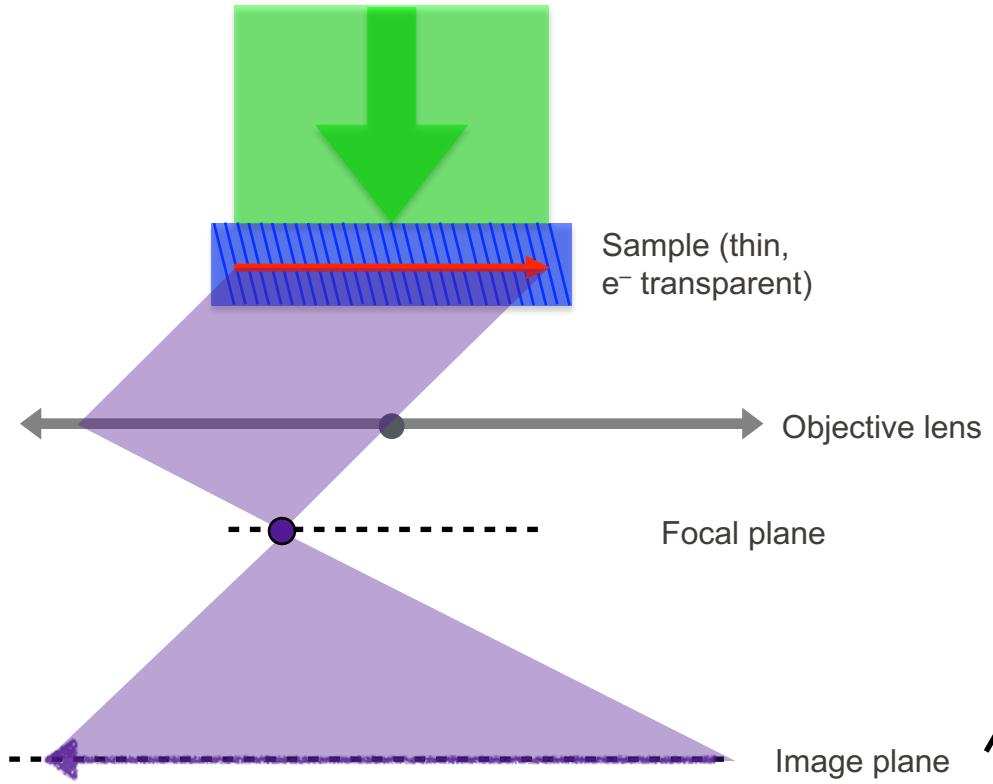


Bright-field image:
made by directly transmitted electrons

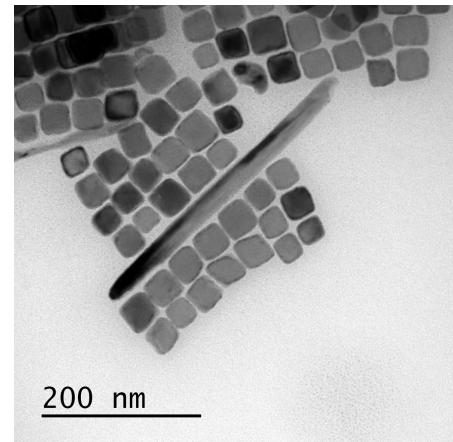
Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$



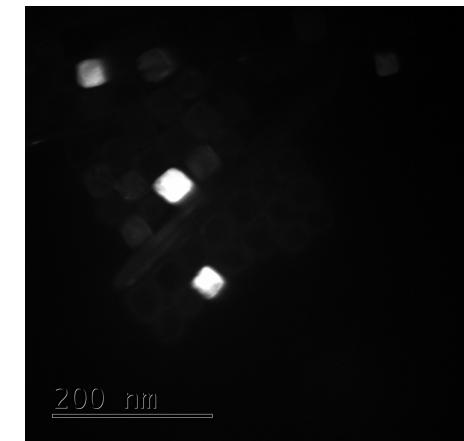
Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$



Bright-field image

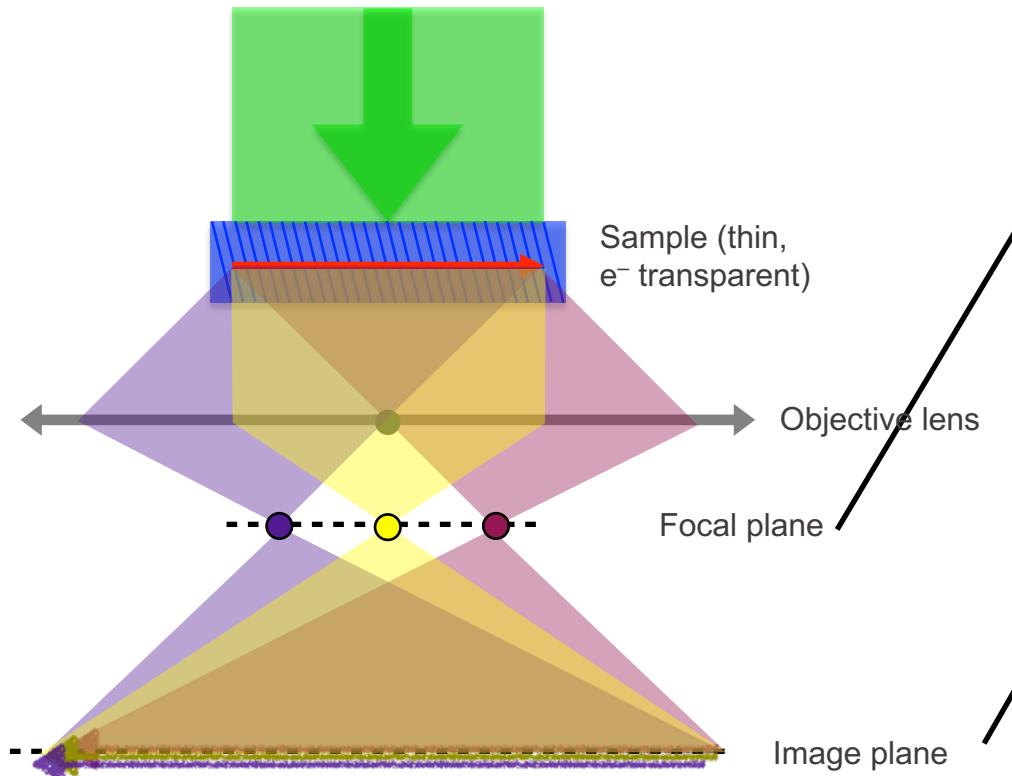


200 nm

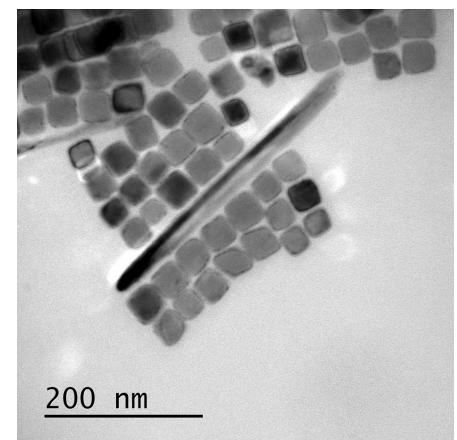
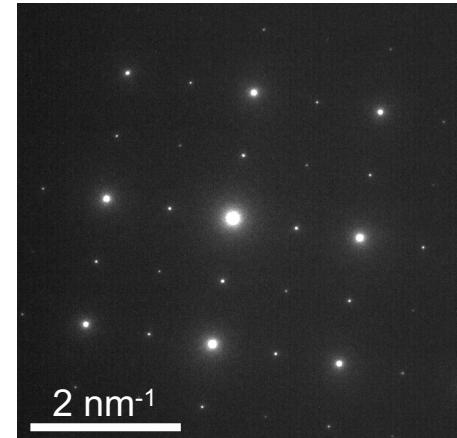


Dark-field image:
made by selected diffracted electrons

Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$

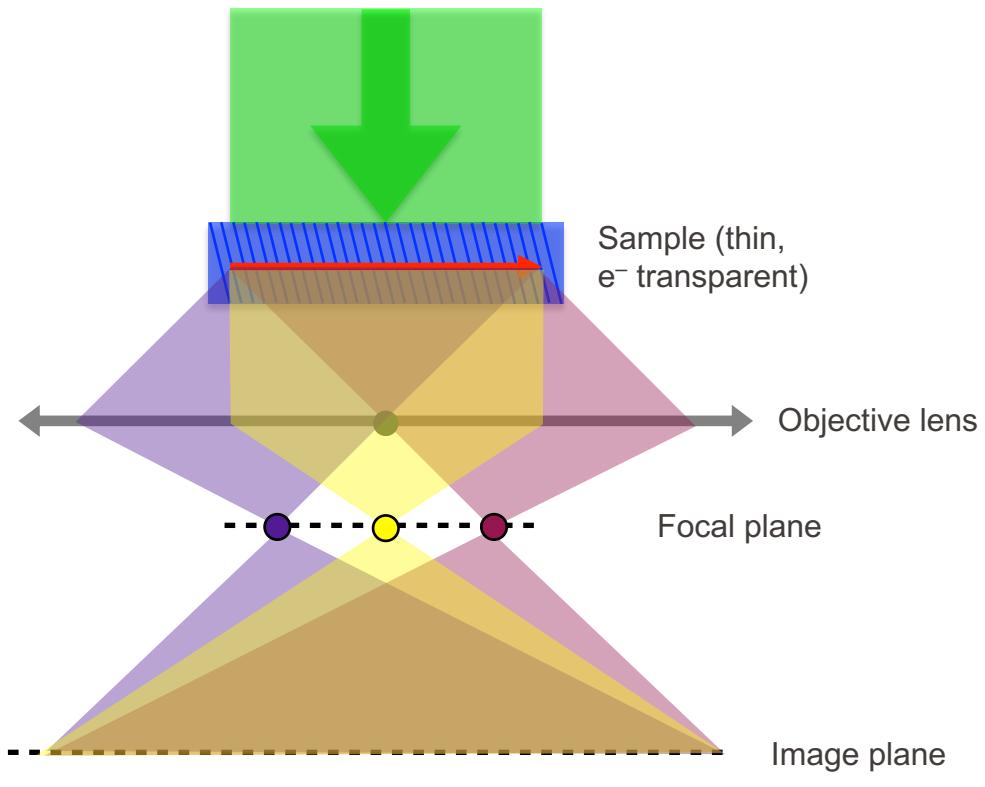


Electron diffraction pattern

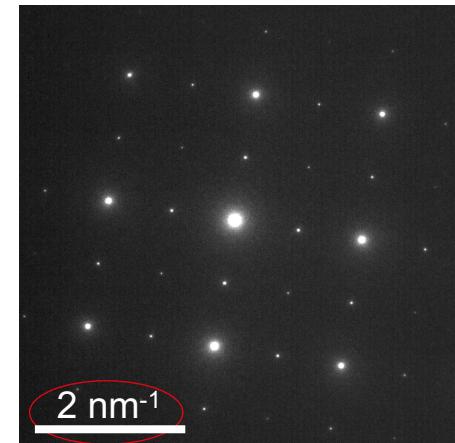


Ghost image:
Superposition of images made
by direct and diffracted electrons

Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$

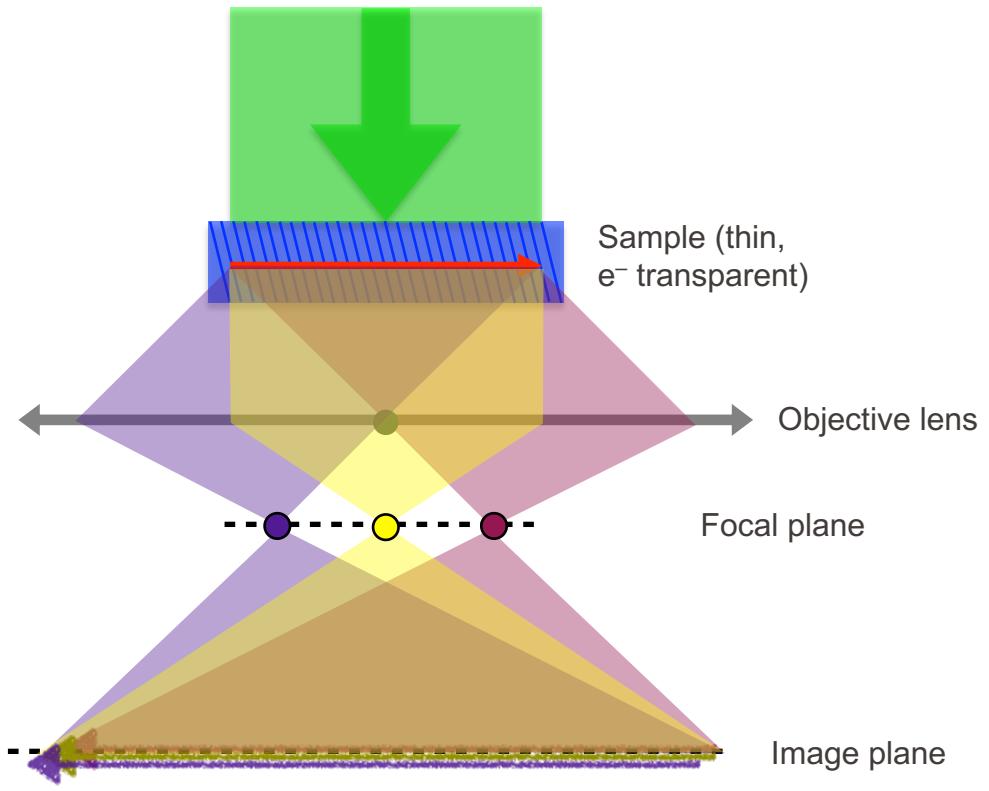


Electron diffraction pattern

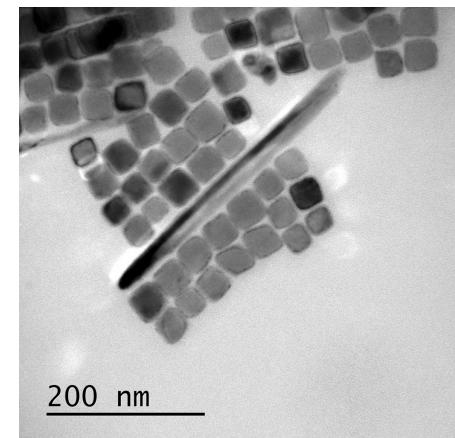
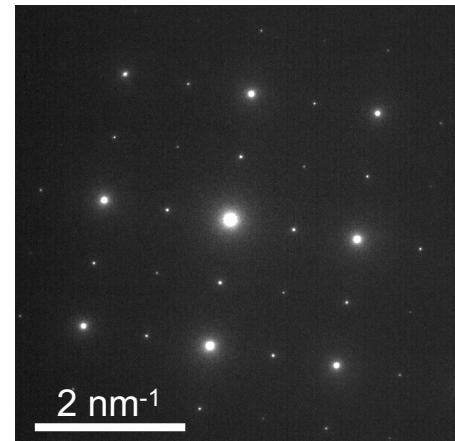


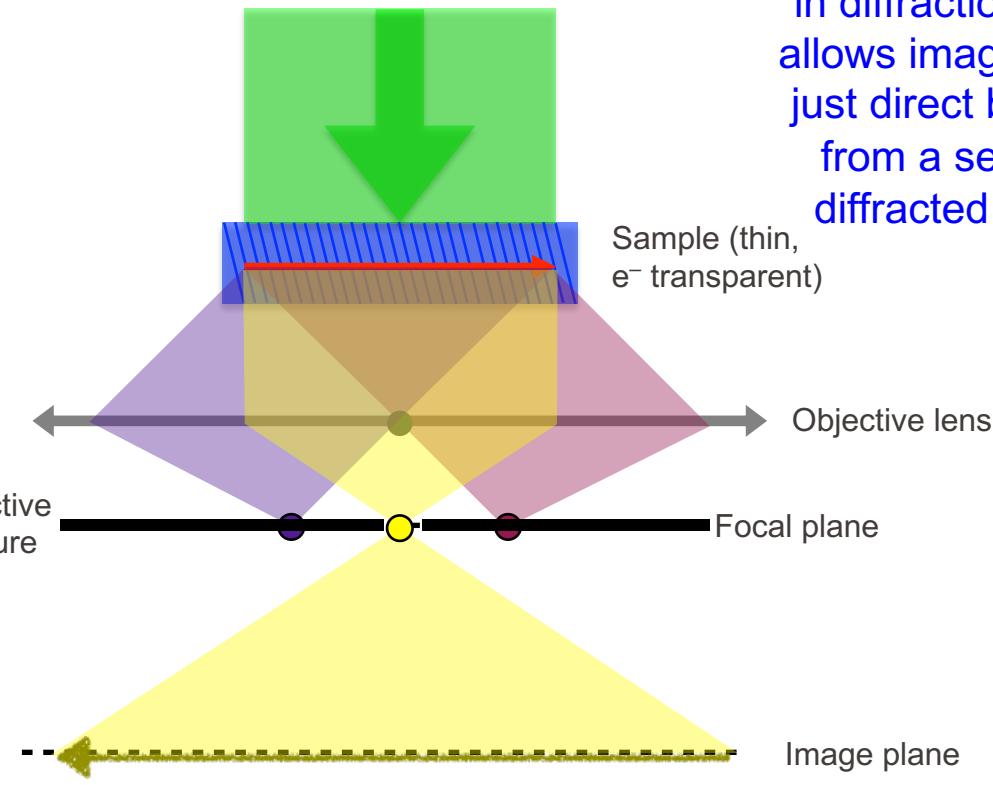
- *In back focal plane of objective lens parallel rays focused to point*
- *Diffraction – coherent scattering – creates sets of parallel rays from different crystal planes*
- *Focusing of these parallel rays in back focal plane creates spots of strong intensity: the diffraction pattern*

Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$

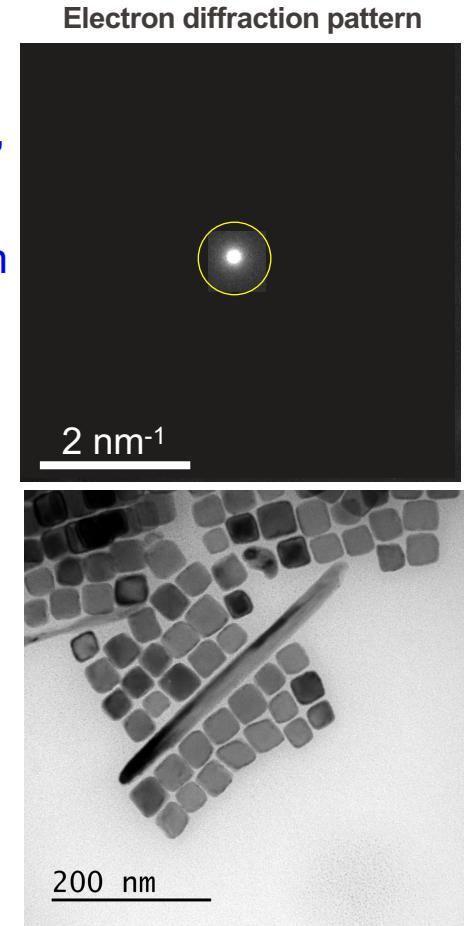


Electron diffraction pattern

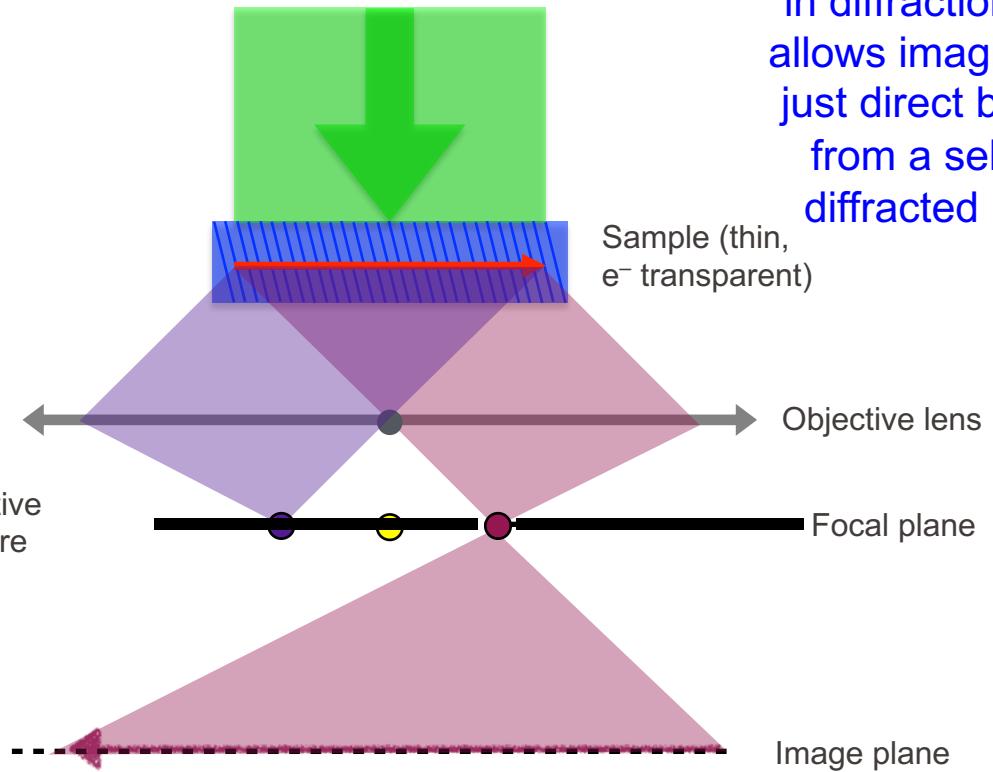




Insertion of the “objective aperture” in diffraction plane allows imaging from just direct beam or from a selected diffracted beam.

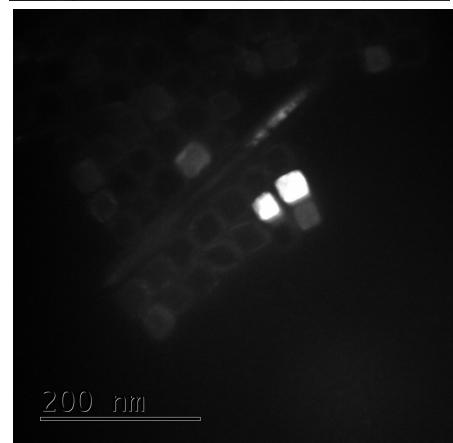
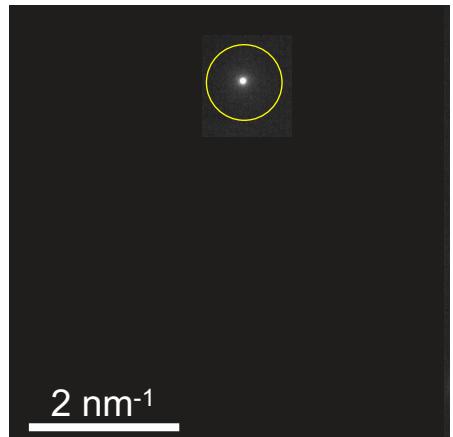


Parallel incident e^- beam; $\lambda \approx 0.02\text{--}0.03 \text{ \AA}$



Insertion of the “objective aperture” in diffraction plane allows imaging from just direct beam or from a selected diffracted beam.

Electron diffraction pattern



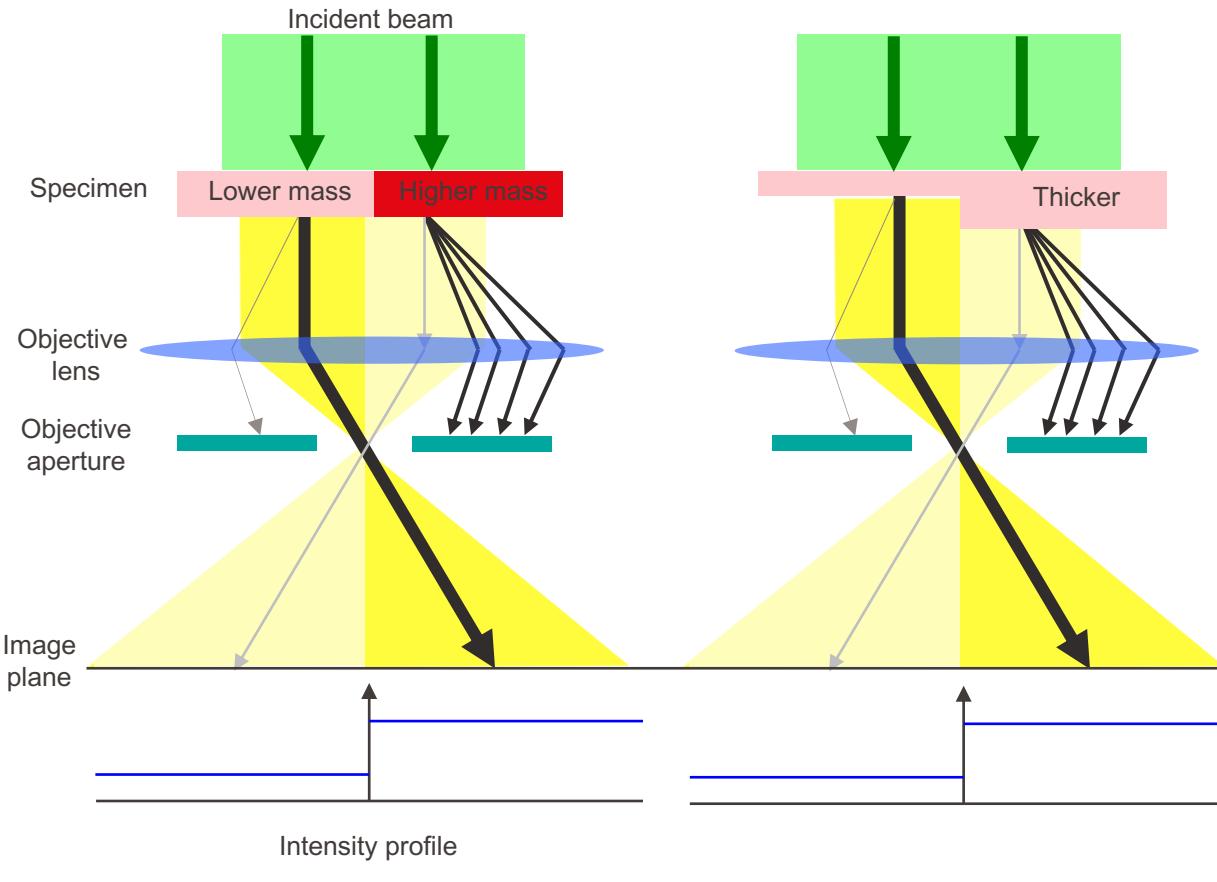
Dark-field image:
made by selected diffracted electrons

▪ Image formation in TEM

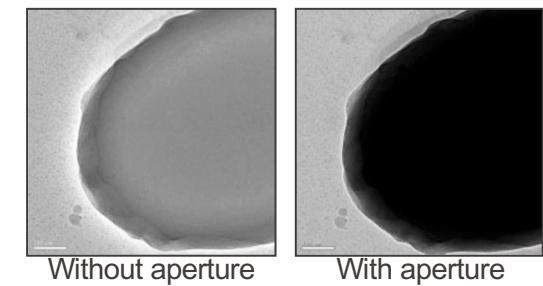
- Image and diffraction modes
- Bright- and dark-field modes
- High-resolution TEM

▪ Image contrast in TEM

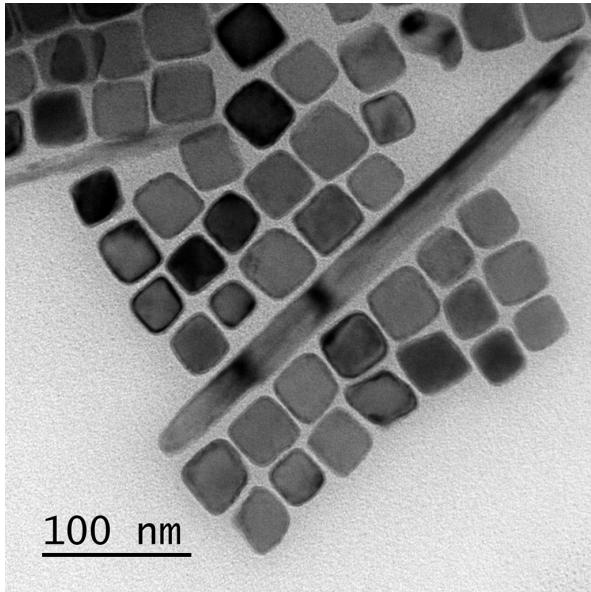
- Mass-thickness contrast
- Diffraction contrast
- Phase contrast



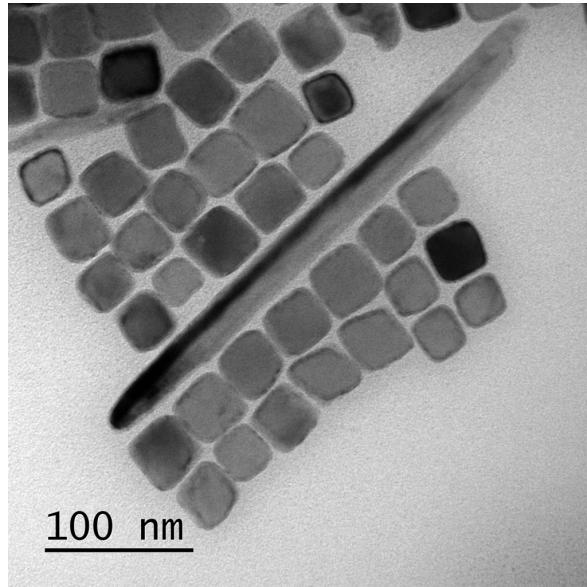
- Areas of higher mass/thickness scatter electrons more than others.
- Electrons are captured by the aperture and lost from the beam path.
- Areas of higher mass thickness will therefore appear dark in the image.
- This is known as:
 - **mass thickness contrast**,
 - **scattering contrast**,
 - **aperture contrast** or
 - **amplitude contrast!**
- Applies to both Crystalline and Amorphous materials.



Example: Copper nano particles

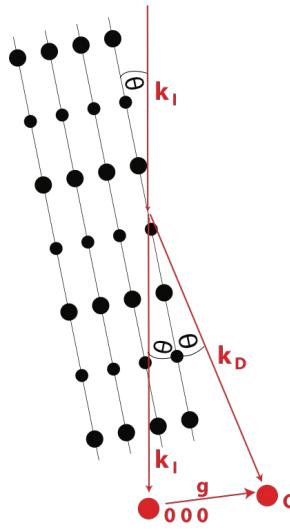


Tilting the sample



Why some of cubic particles appear darker than others?

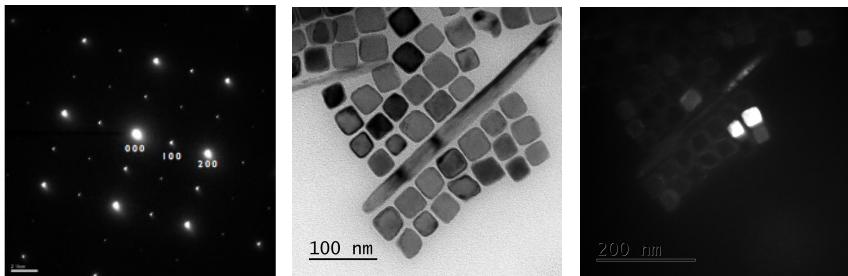
Note that contrast changes when tilting the specimen



Path difference between reflection from planes distance d_{hkl} apart
 $= 2d_{hkl} \sin\theta$

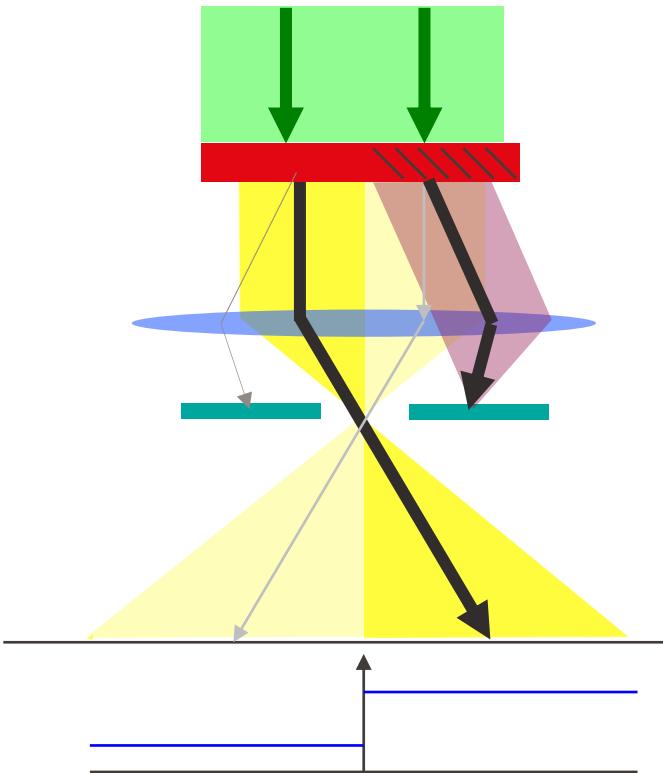
Bragg law: $\lambda = 2d_{hkhkl} \sin\theta$

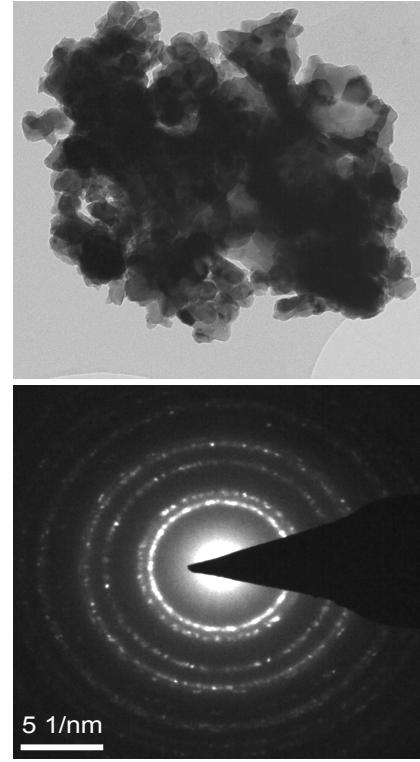
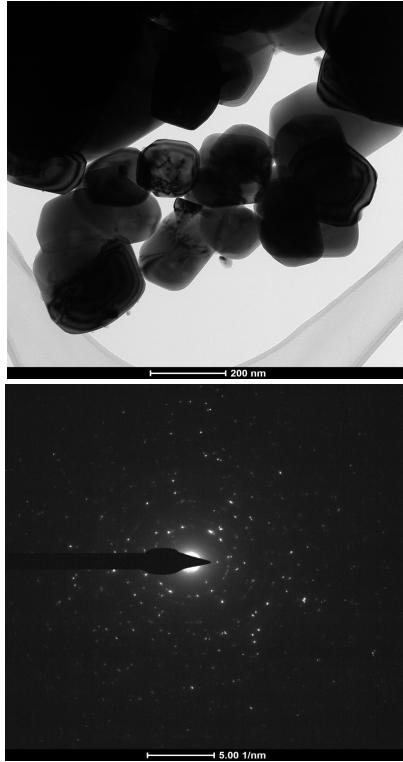
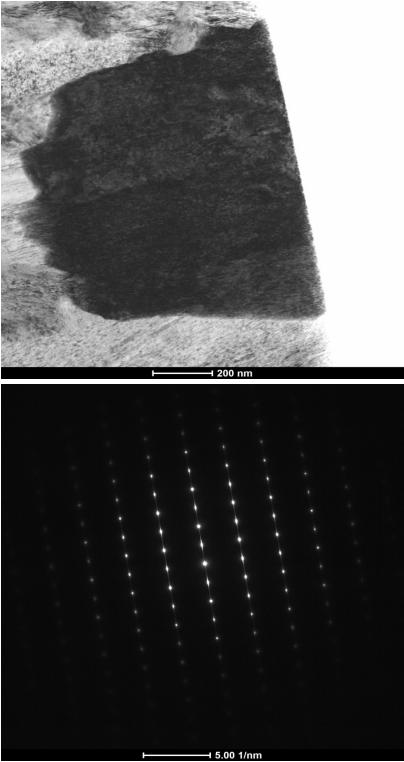
→ Bragg diffraction at angle 2θ



TEM gives image & diffraction information!

Diffraction contrast





Principle of diffraction contrast imaging:

Typically we use an objective aperture to select either the direct beam or a specific diffracted beam in the back-focal plane.

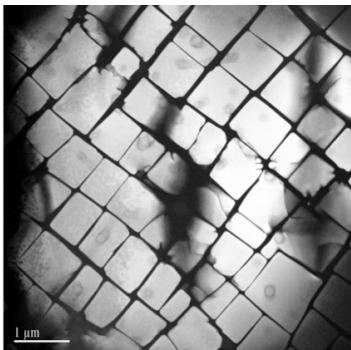
If the diffraction condition changes across the sample the intensity in the selected beam changes; the intensity in the image changes correspondingly.

In other words we make a spatial map of the intensity distribution across the sample in the selected beam: *it is a mapping technique.*

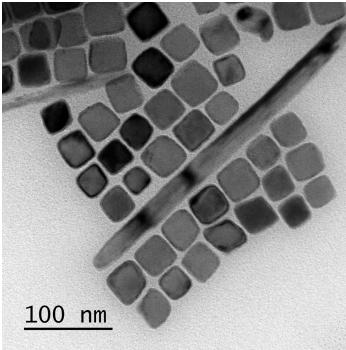
In this way we can image changes in crystal phase and structural defects such as dislocations

As an example such TEM imaging was a key piece of evidence proving the existence of dislocations

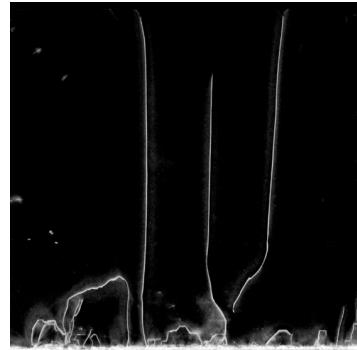
Examples of diffraction contrast image



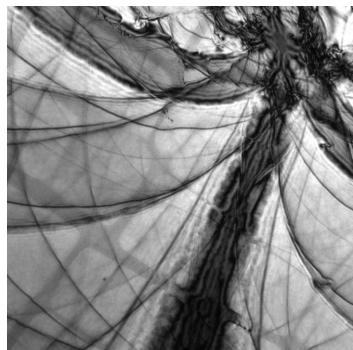
Dark-field (DF) image
Precipitates in NiAl super-alloy



Bright-field (BF) image
Cu Nanocubes



Weak beam dark-field image
Dislocations in GaN



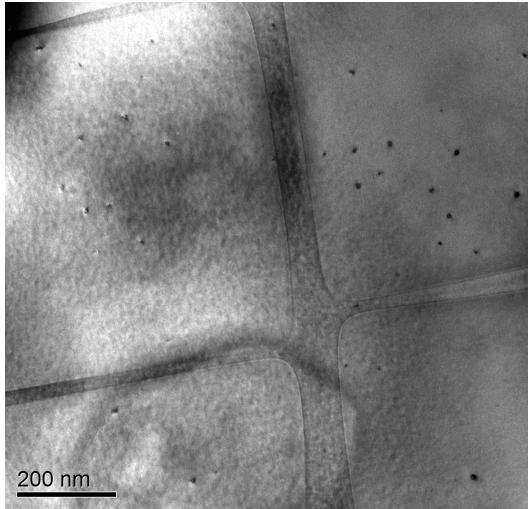
Bright-field image of bent
regions in NiAl super-alloy
= Bend contours



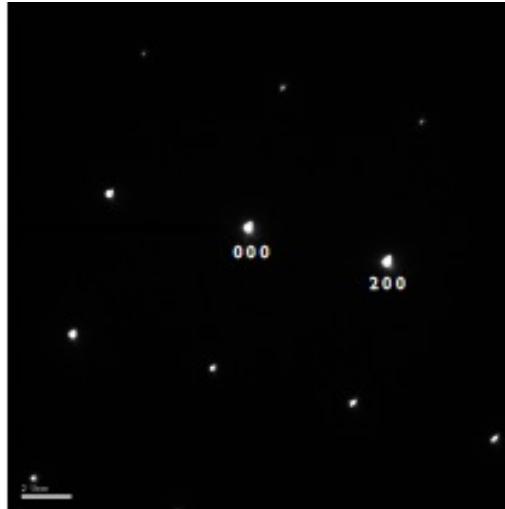
Thickness fringes in BF-TEM
image of a Cu nanocube

Example: Ni₃Al-based superalloy

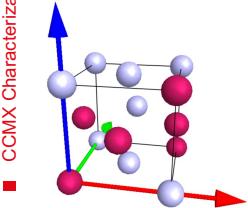
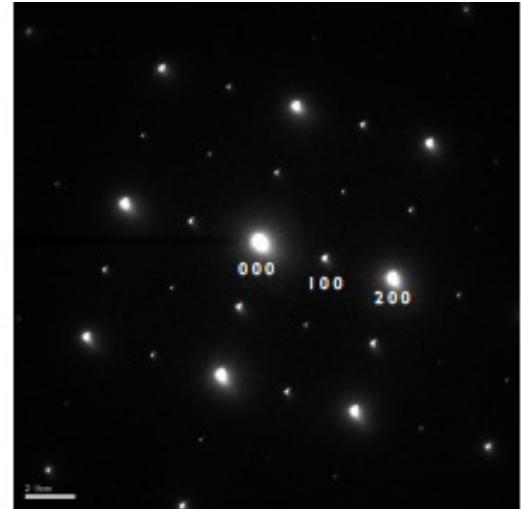
Bright-field



γ -phase matrix: FCC
(Ni, Al disordered on sites)

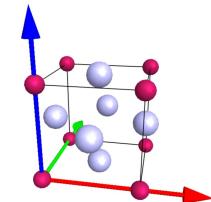


γ' -phase precipitate: primitive cubic
(Ni on face centres, Al on corners)



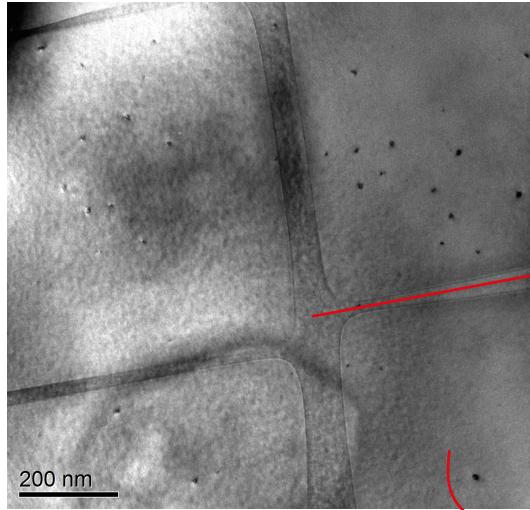
Which reflection to use to discriminate the the γ' -phase precipitate from the matrix?

- a) {200} of γ' -phase precipitate
- b) {200} of γ -phase matrix
- c) (000) direct beam
- d) {100} of γ' -phase precipitate

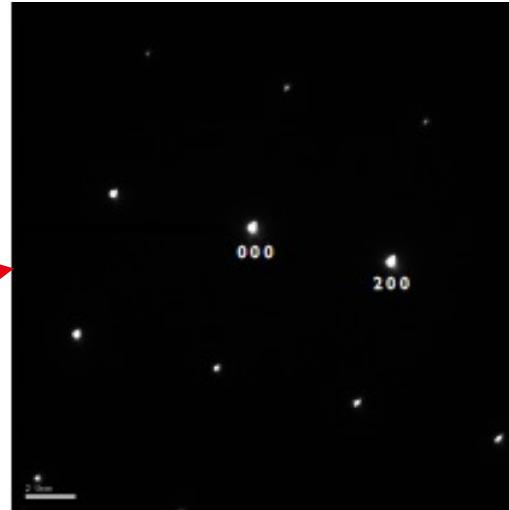


Example: Ni₃Al-based superalloy

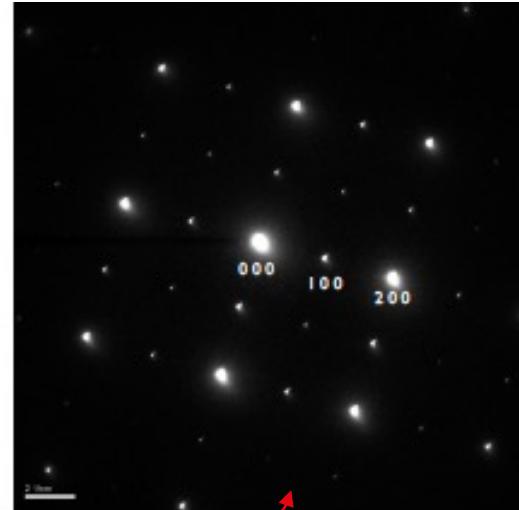
Bright-field

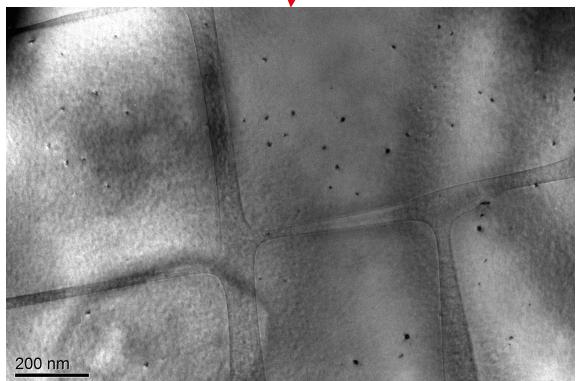
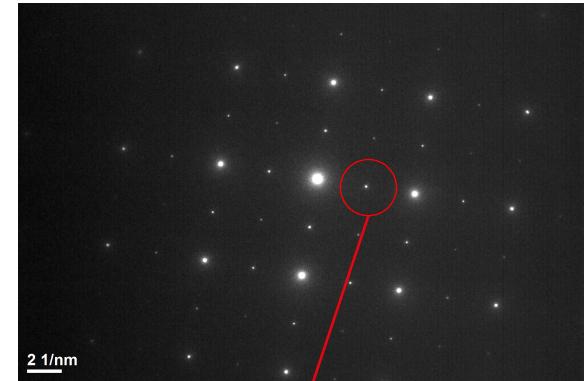
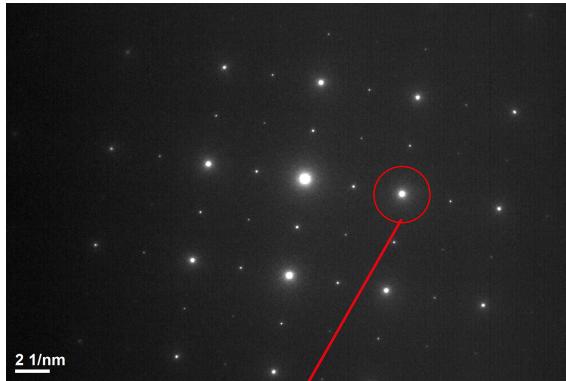
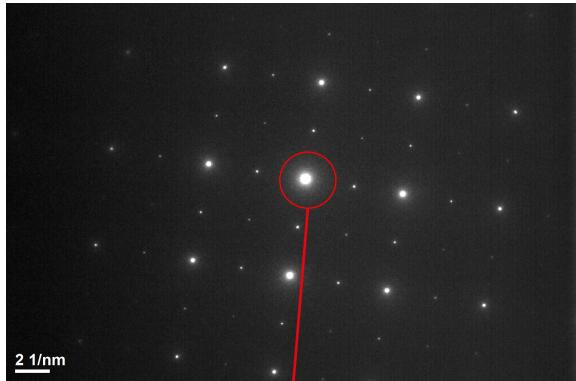


γ -phase matrix: FCC
(Ni, Al disordered on sites)

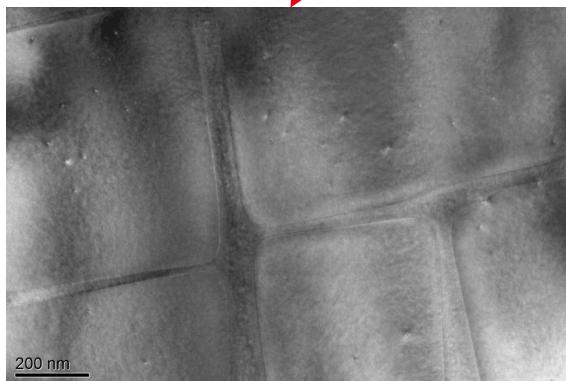
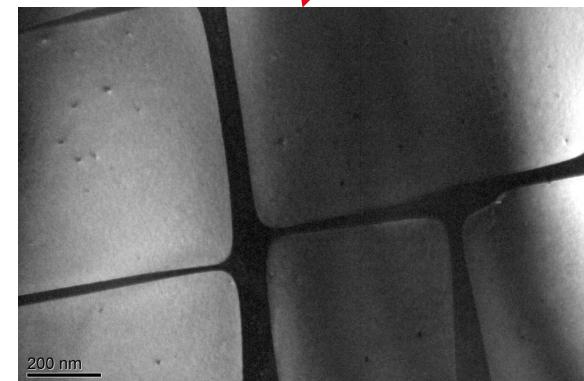


γ' -phase precipitate: primitive cubic
(Ni on face centres, Al on corners)

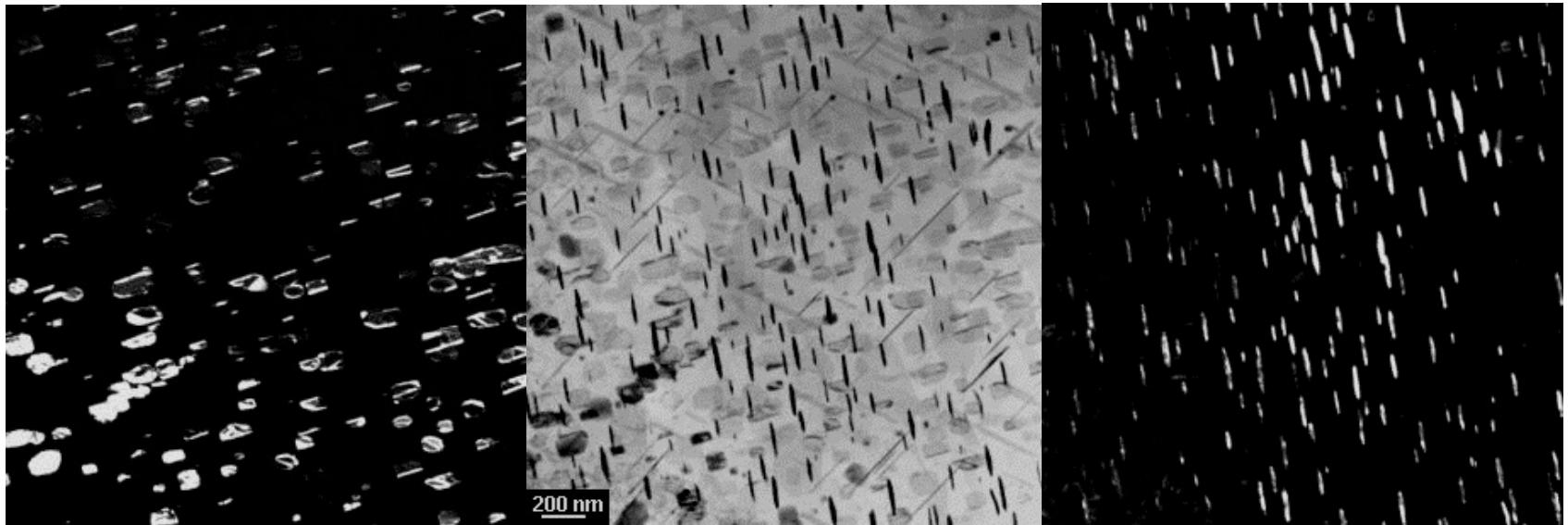


Example: Ni₃Al-based superalloy

Bright-field image

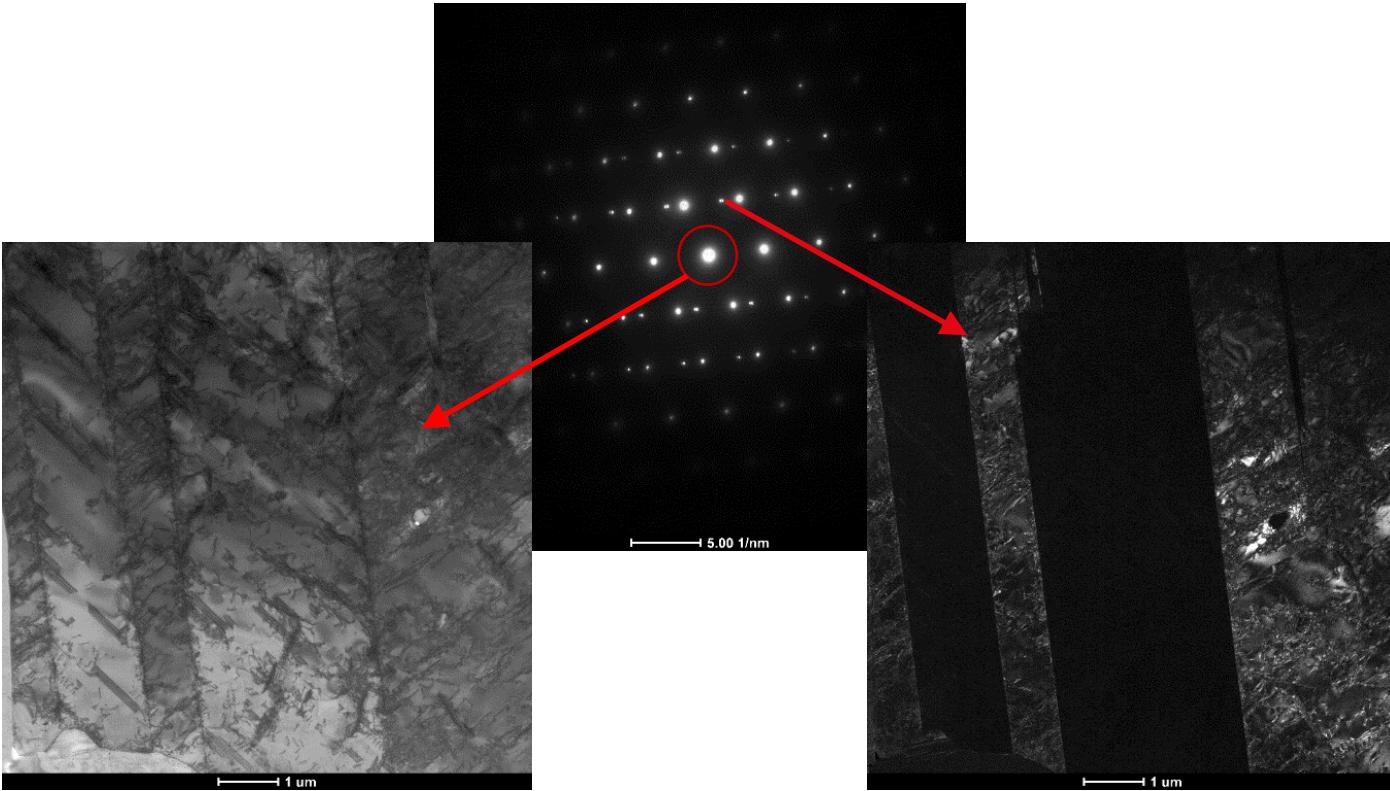
Dark-field image $\mathbf{g} = (2\ 0\ 0)$ Dark-field image $\mathbf{g} = (1\ 0\ 0)$

Example: Aluminum alloy containing precipitates with preferential growth direction

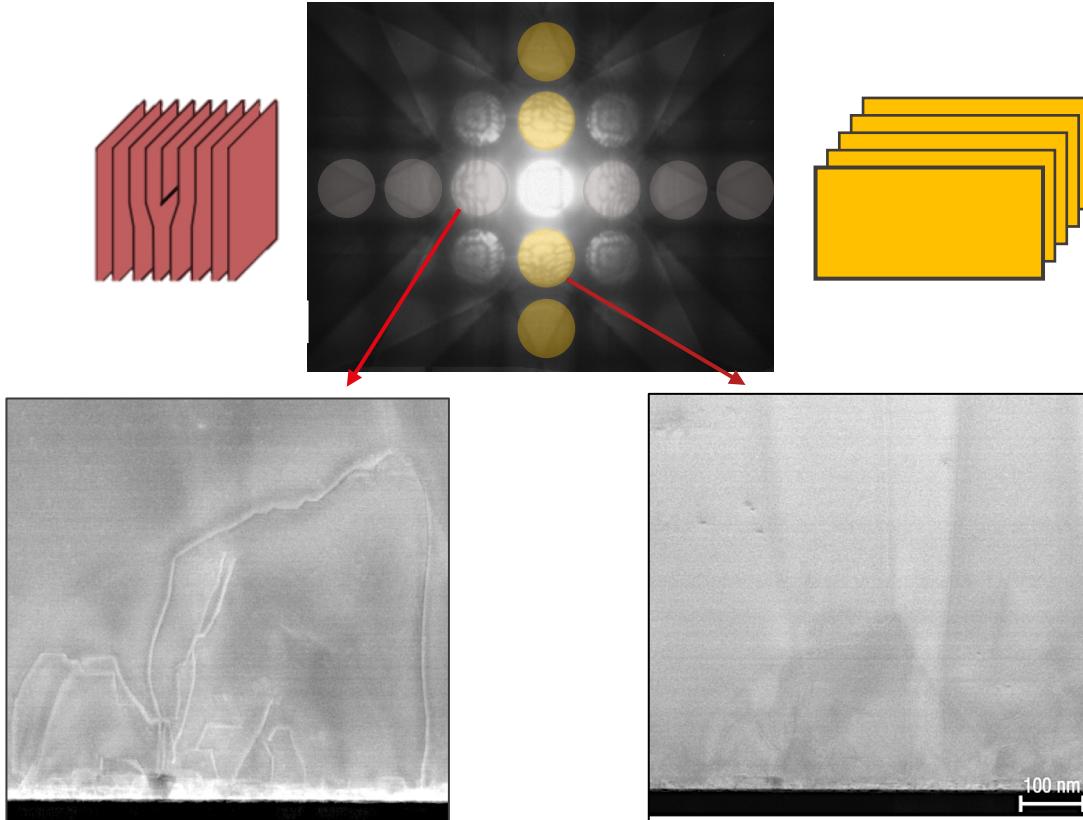


Orientation relationship between the matrix and precipitates can be determined

Twinning in electron diffraction



Exemple: Dark-field images of dislocations in GaN thin film on sapphire



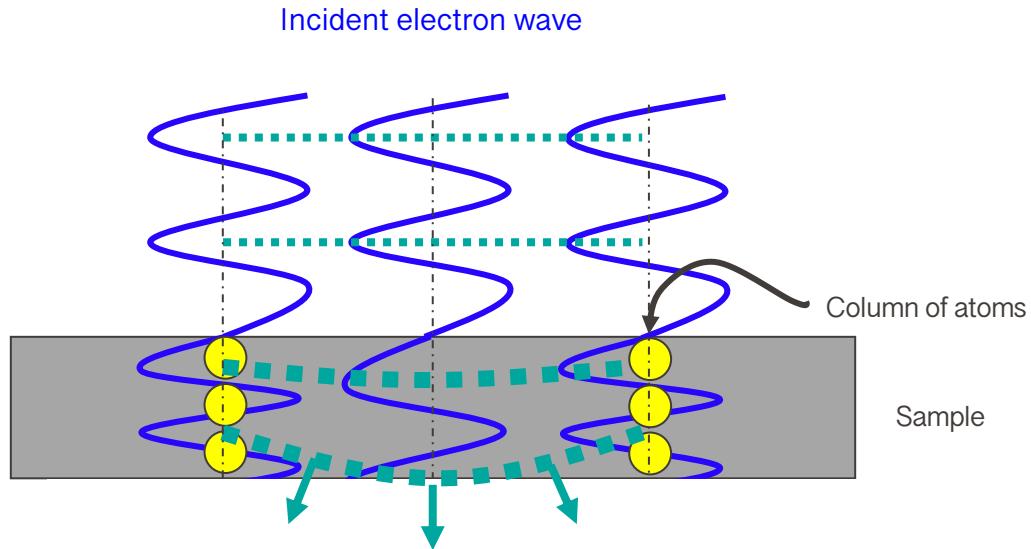
▪ **Image formation in TEM**

- Image and diffraction modes
- Bright- and dark-field modes
- High-resolution TEM

▪ **Image contrast in TEM**

- Mass-thickness contrast
- Diffraction contrast
- Phase contrast

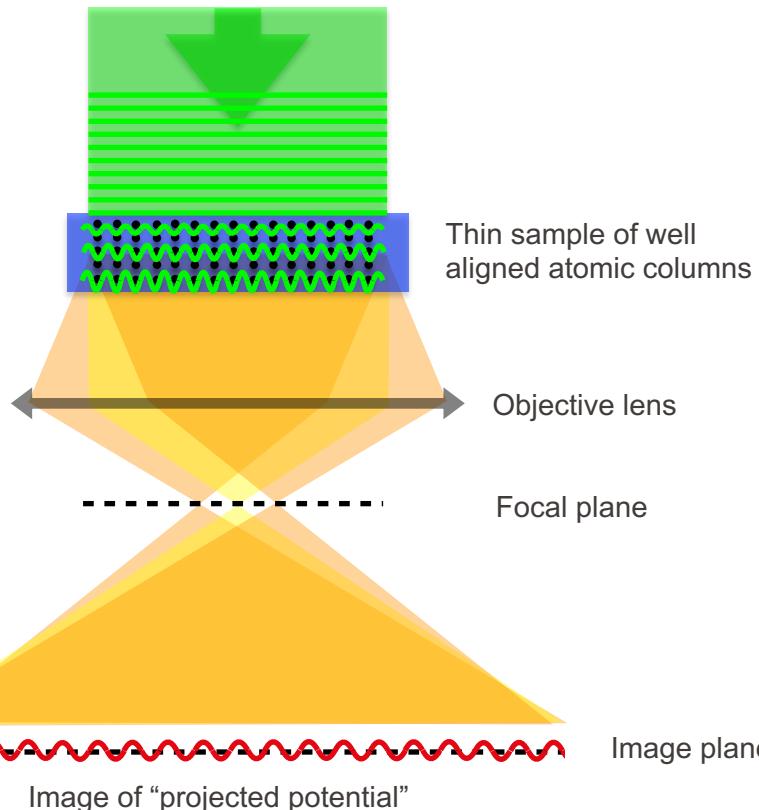
What happens when an electron wave passes through the sample?



Variations in the projected potential produce local relative phase shifts of the electron wave. The wave front therefore bends as wave travels through medium.

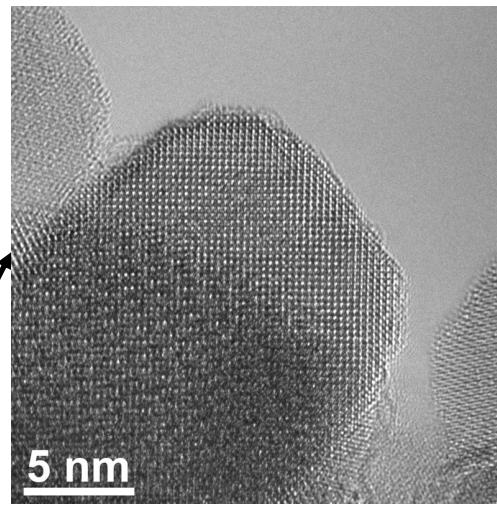
The direction of propagation of the electron may change! \Rightarrow Diffraction!

Coherent incident plane wave front



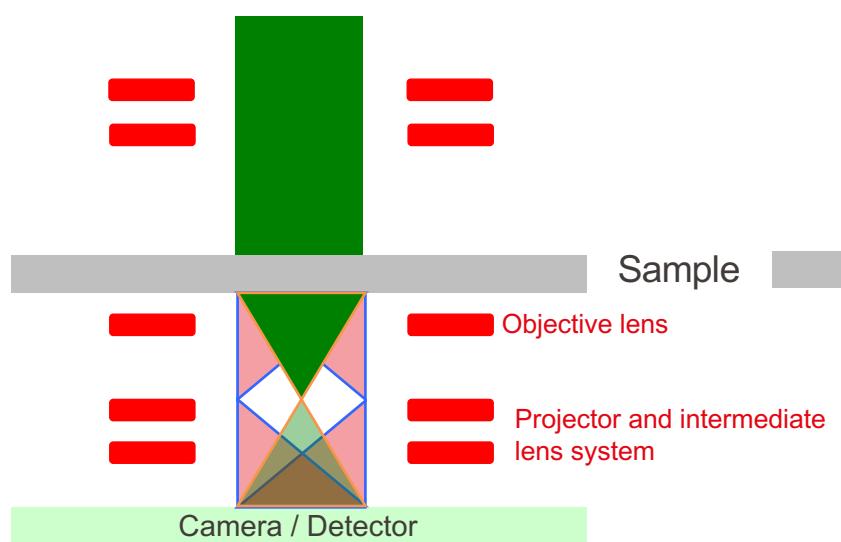
Due to changes in sample thickness and orientation, as well as lens imperfections, image interpretation is complex.

Resist the temptation of interpreting the spots as atoms!



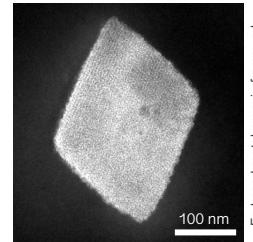
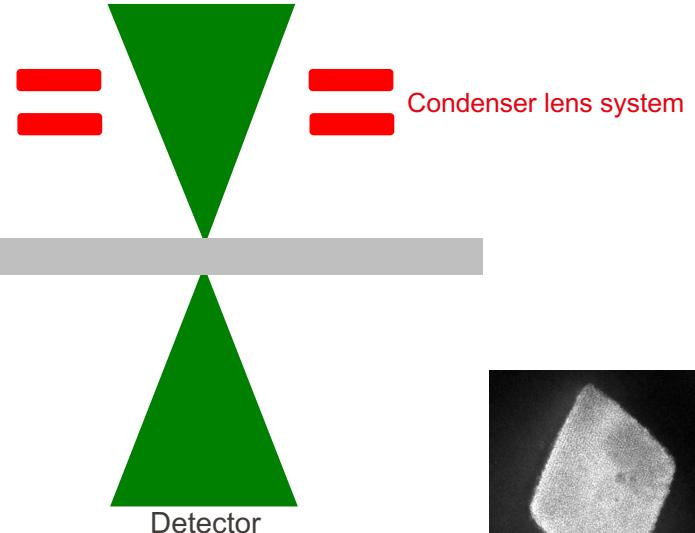
TEM operation modes

Conventional TEM

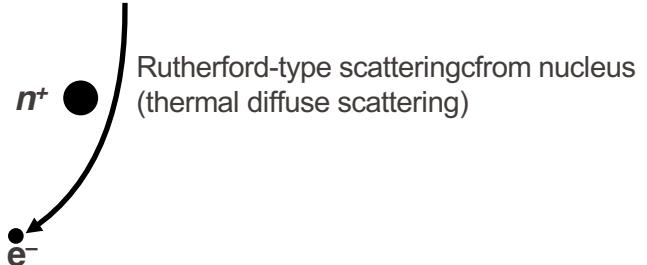
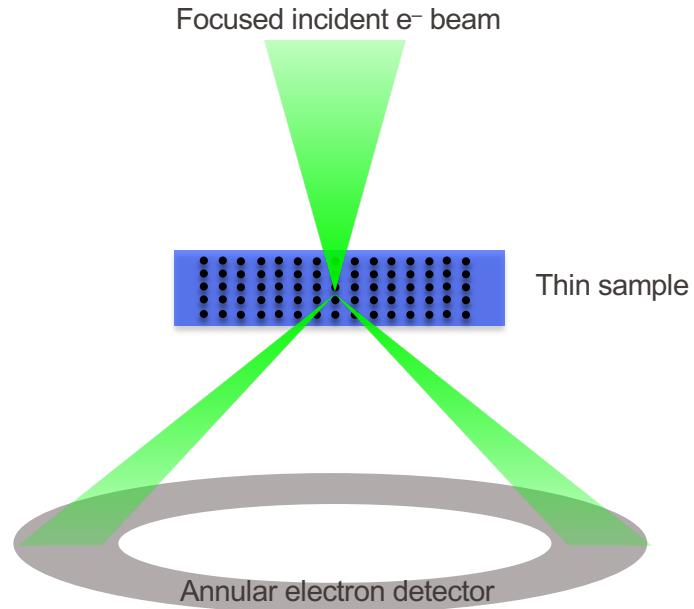


Scanning mode (STEM)

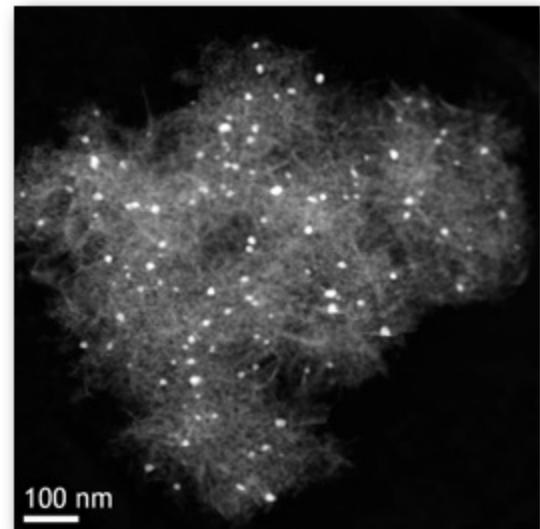
Electron beam (30-300 keV)



Scanning TEM (STEM) with focused probe

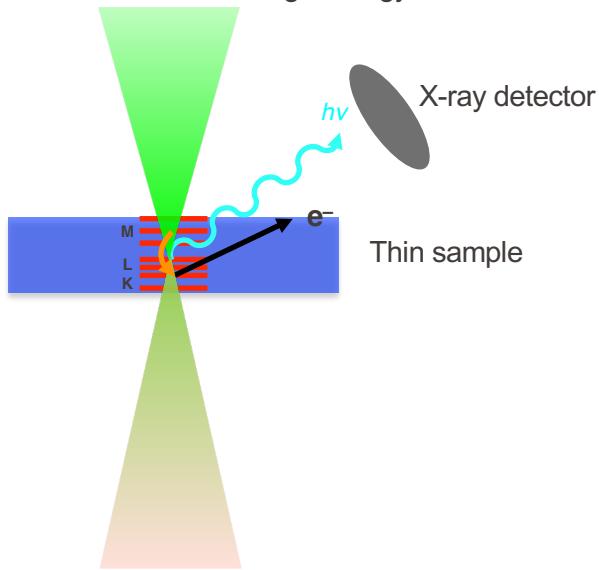


High-angle annular dark-field (HAADF) image



Mass/thickness contrast image

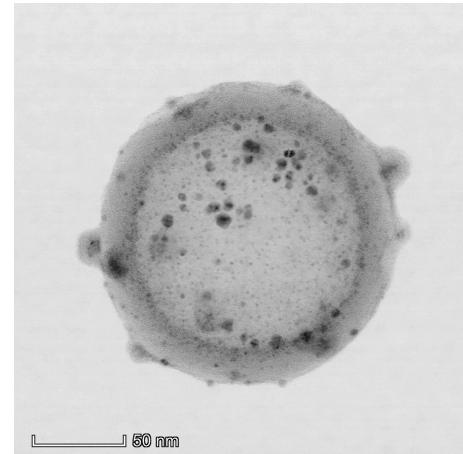
Focused incident e^- beam: high energy!



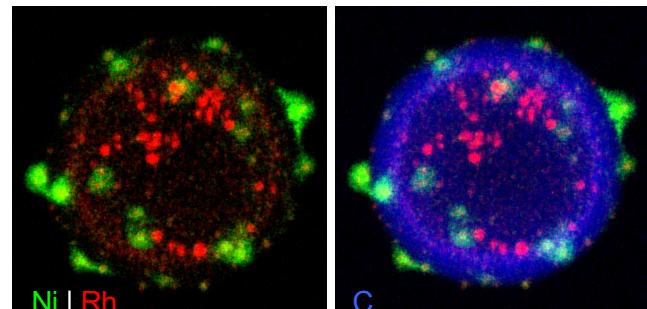
Transmitted beam suffers energy loss → Used in EELS

- High energy incident electrons (ballistic) → Ejection of inner shell e^-
- Upper shell e^- descends
- Transition energy emitted as X-ray;
Characteristic of element | $E_{X\text{-ray}} = E_{\text{Upper shell}} - E_{\text{Inner shell}}$

Bright-field STEM image



Ni-Rh catalytic nanoparticles in carbon shell



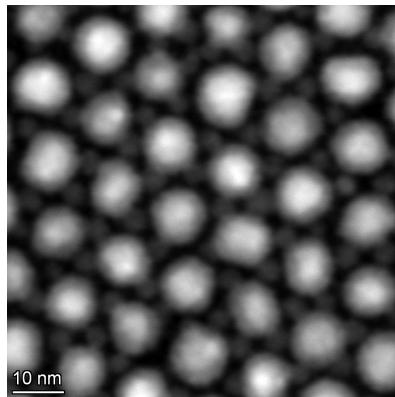
Map X-ray intensity as function of probe position (x,y)

With fast mapping STEM-EDX has become a regular feedback tool for materials synthesis

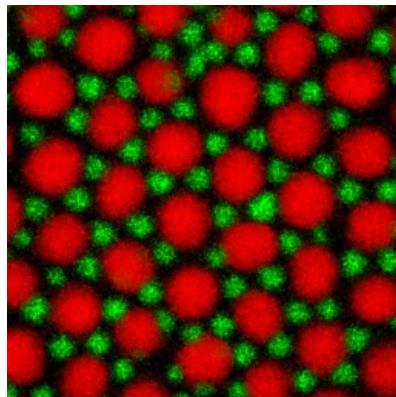
Sample characterized in a couple of minutes/hours

With aberration-corrected STEM, atomic resolution EDX became possible

Example : Assembly of Fe_3O_4 and Cu particles

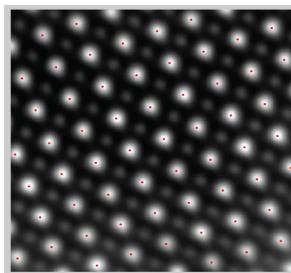


HAADF image

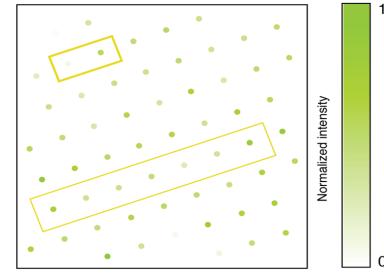


Map of Cu and Fe

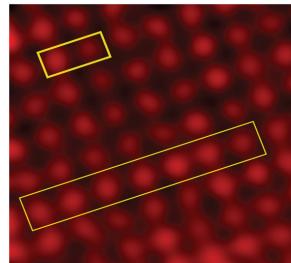
Example: $(\text{Ba}_x\text{Sr}_{1-x})\text{TiO}_3$



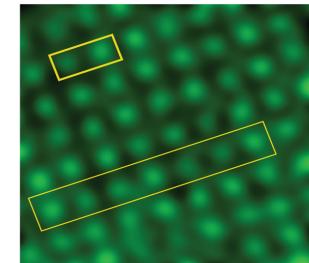
HAADF image



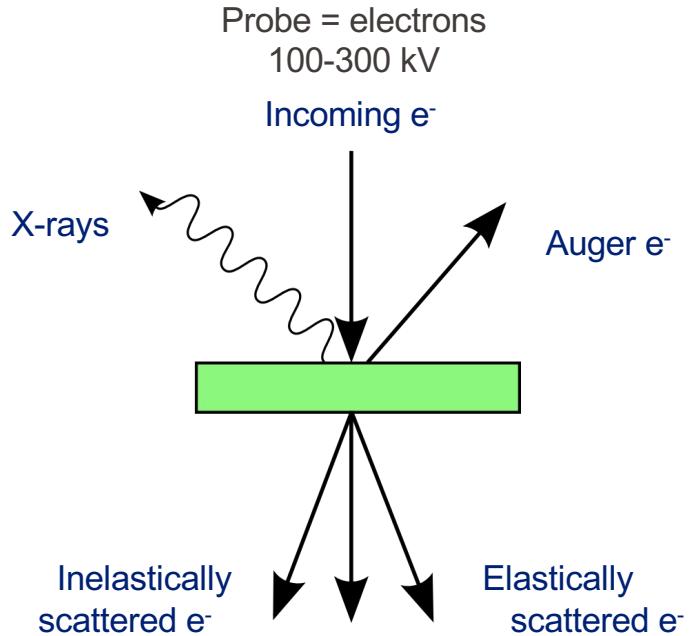
Intensity map



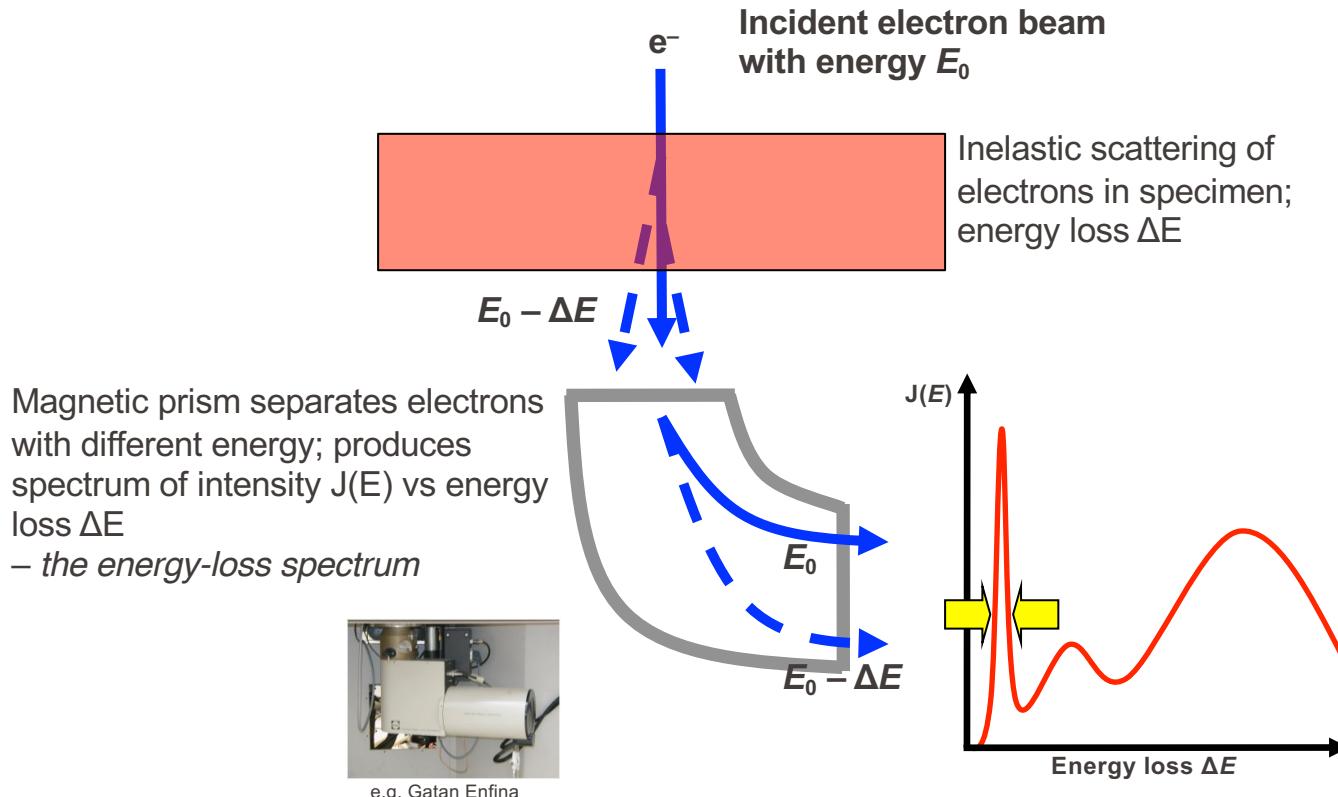
Map of Sr and Ba

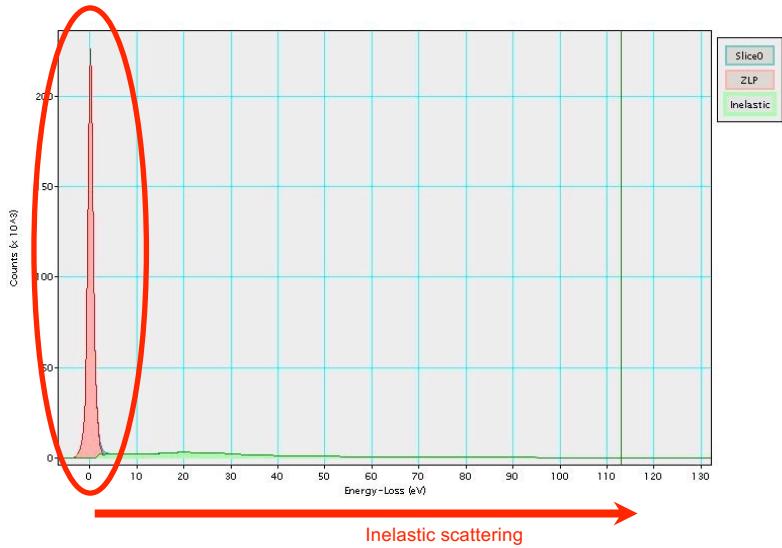


The TEM specific microanalysis technique!



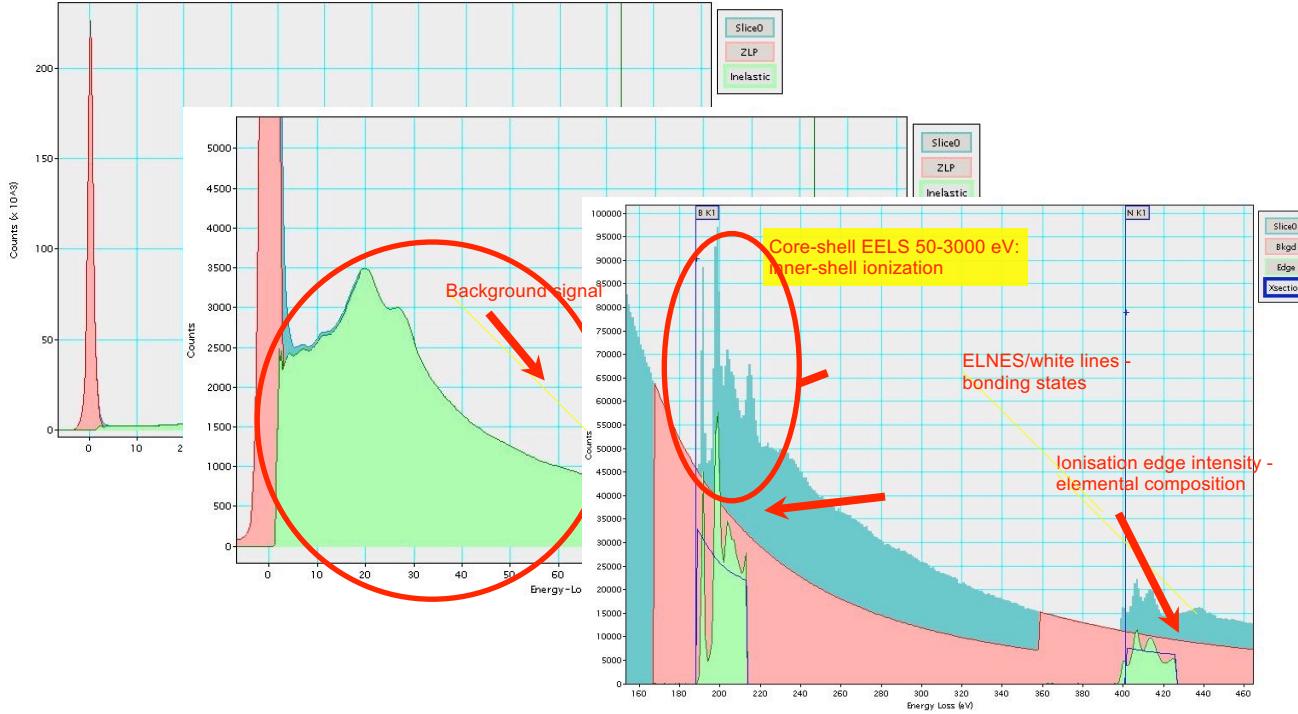
Principle of energy-loss spectrometry







Interaction with outer electrons (conduction/valence)
Low-loss spectrum 0-50 eV: valence excitations -
plasmons (bulk & surface),
band gaps, optical properties

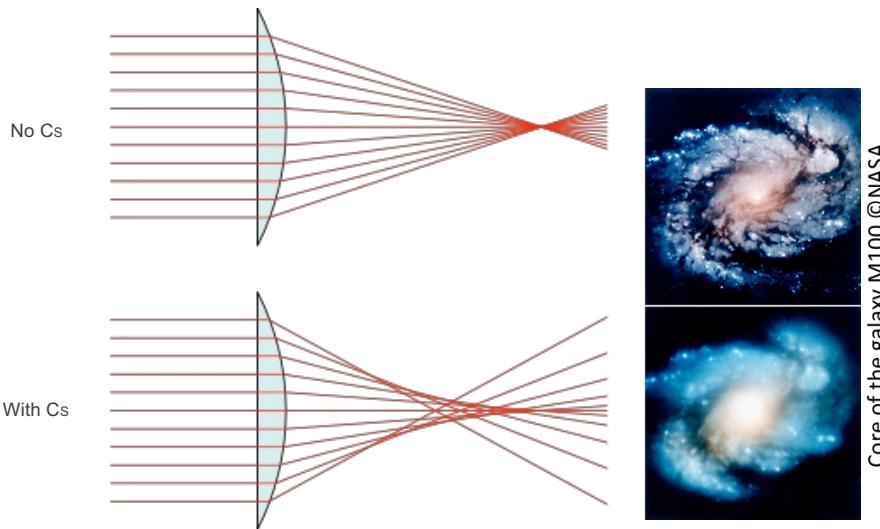


Limitation to spatial resolution: Lens aberrations

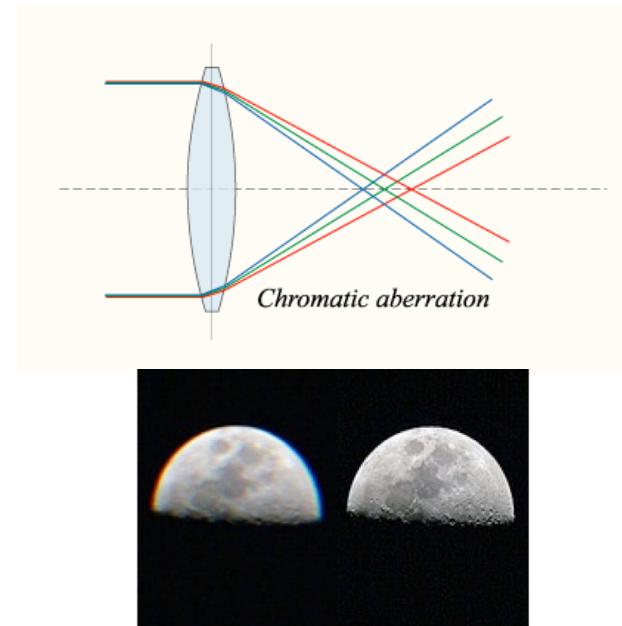
Electromagnetic lenses in TEM column are toroidal

Lenses inherently convergent

→ Spherical aberration (C_s) and Chromatic aberration (C_c)



Parallel rays that pass through the central region of the lens focus farther away than the rays that pass through the edges of the lens. Results in multiple focal points and thus a blurred image.

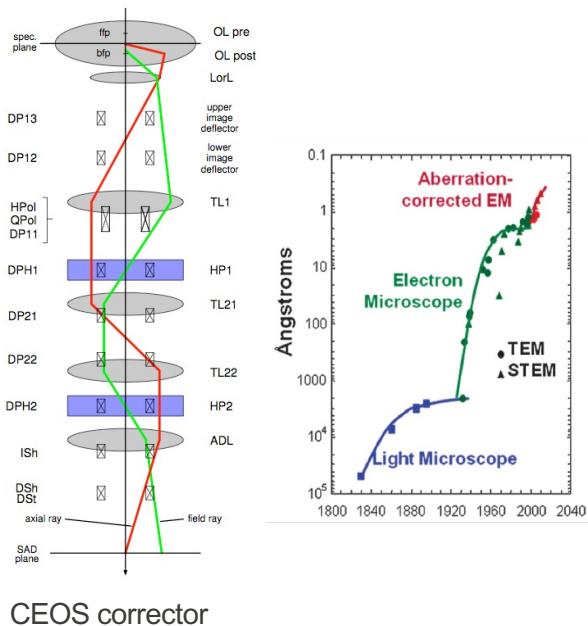


Lens cannot focus all energies (wavelengths) to the same convergence point.

Resolution in TEM limited by aberrations, especially C_s

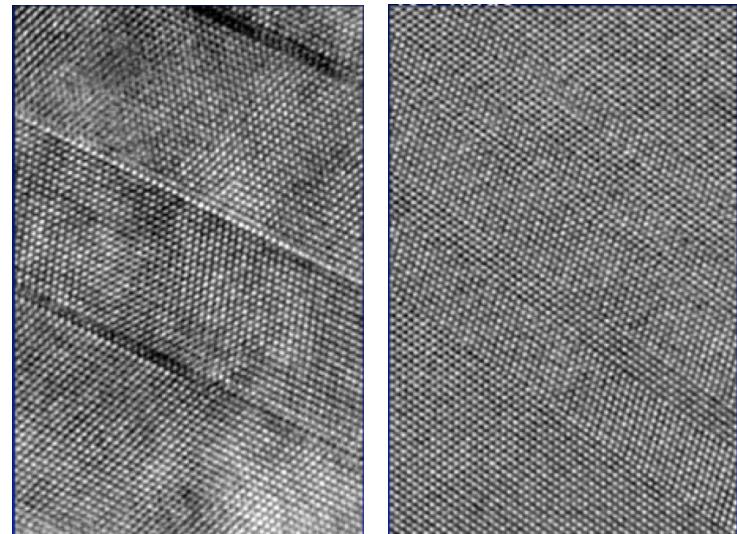
Combination of standard radially-symmetric convergent lenses with multipole divergent lenses (e.g. tetrapoles, hexapoles) to tune Cs

Like “glasses” for TEM (or the Hubble)



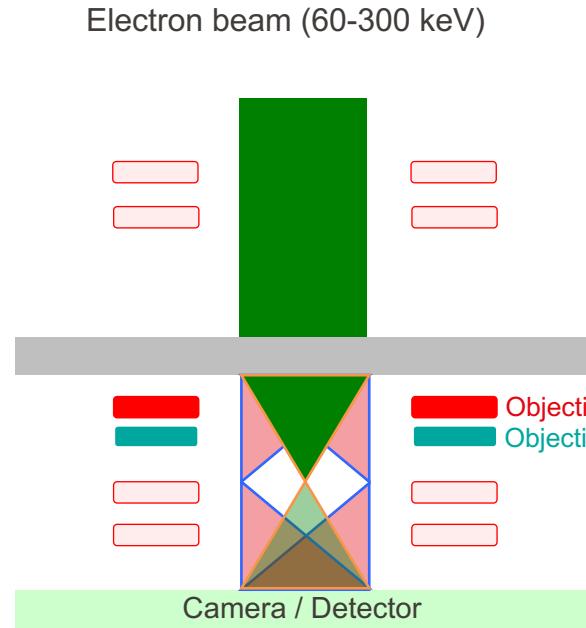
→ Resolution jumps to sub-Å!

Example: $\Sigma 3$ grain boundaries in Al
Uncorrected Cs-corrected

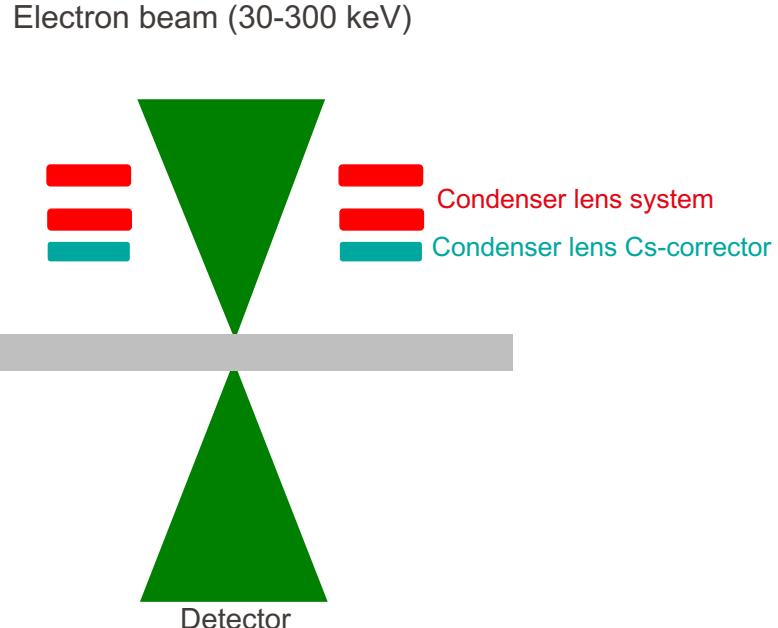


Images: Oikawa, JEOL

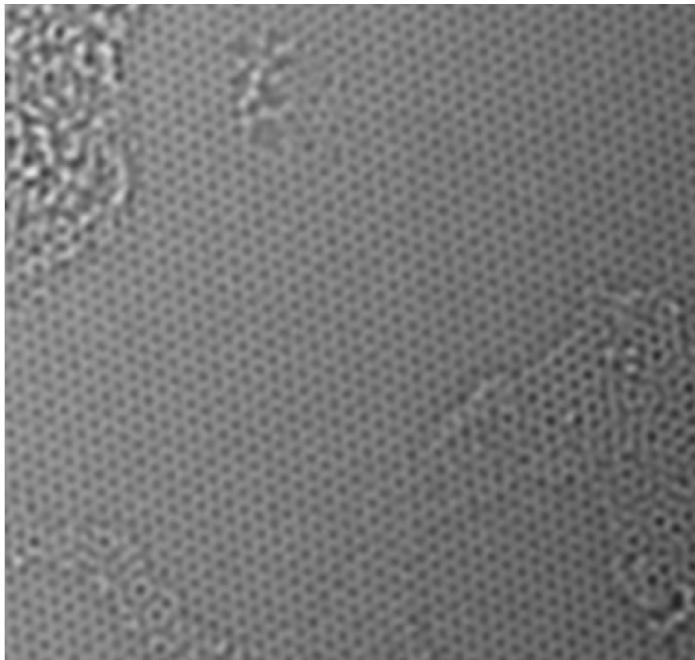
TEM (Image-corrected)



STEM (Probe-corrected)



- Cs-correction and monochromatic illumination to reduce C_c allow sub-Å resolution even at lower kV where electron wavelength λ is greater
- Beam sensitive, low contrast materials can be imaged
- Here a monolayer graphene is imaged with 80 keV, monochromated e^-



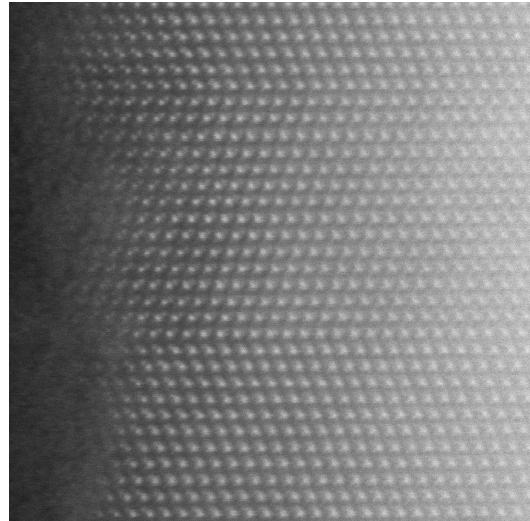
Example: (Al)GaAs nanowires imaged at 300 kV in STEM mode

HR-STEM with sub-Å Cs-corrected probe:

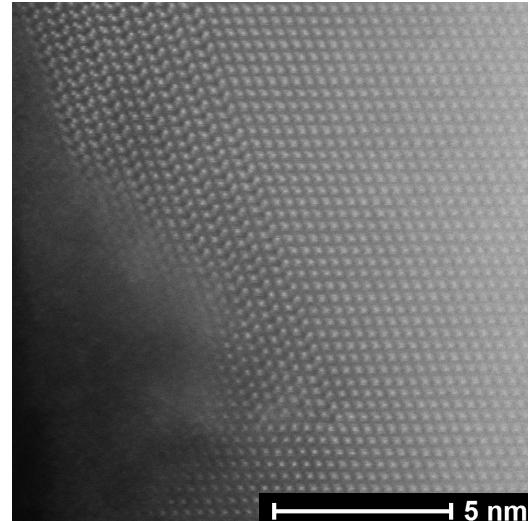
Simple (quantitative) atomic column contrast

Reduced sensitivity to small changes in sample orientation

Image either in focus or out of focus (no contrast reversals with defocus, thickness)

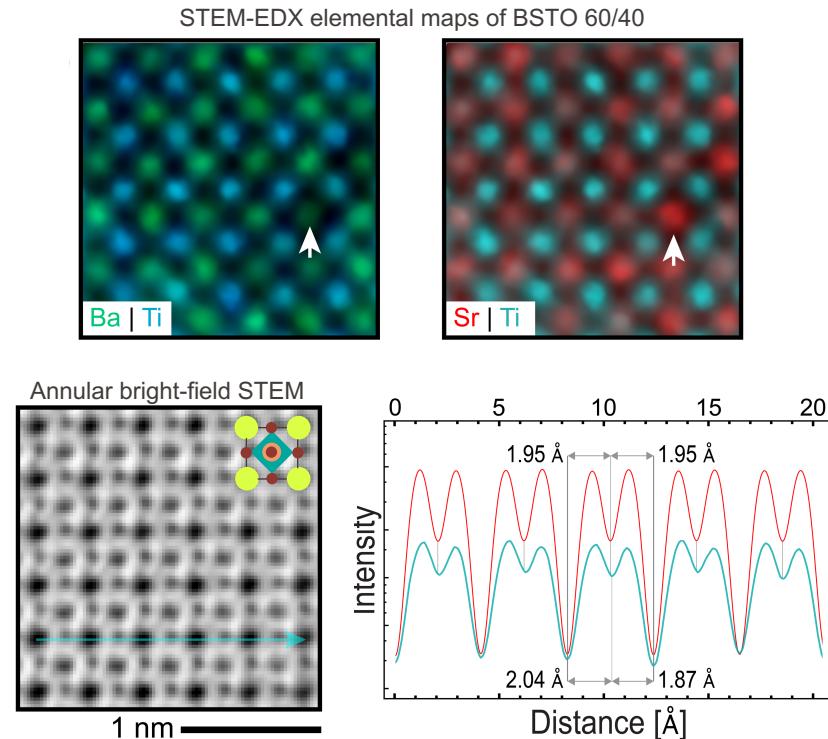
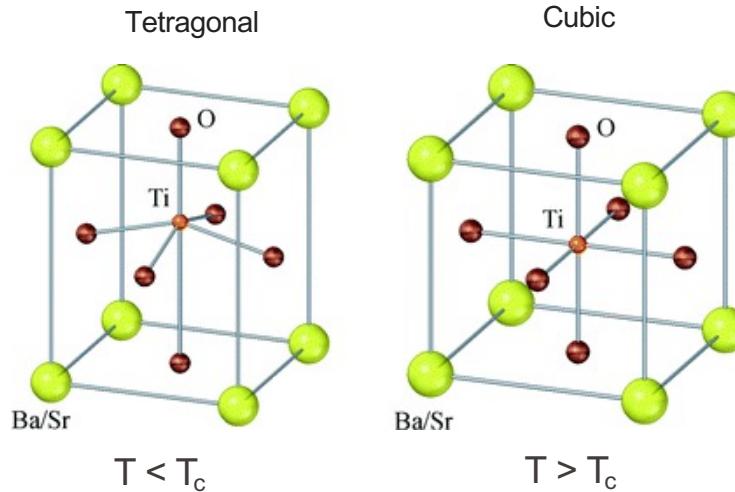


FCC twinning



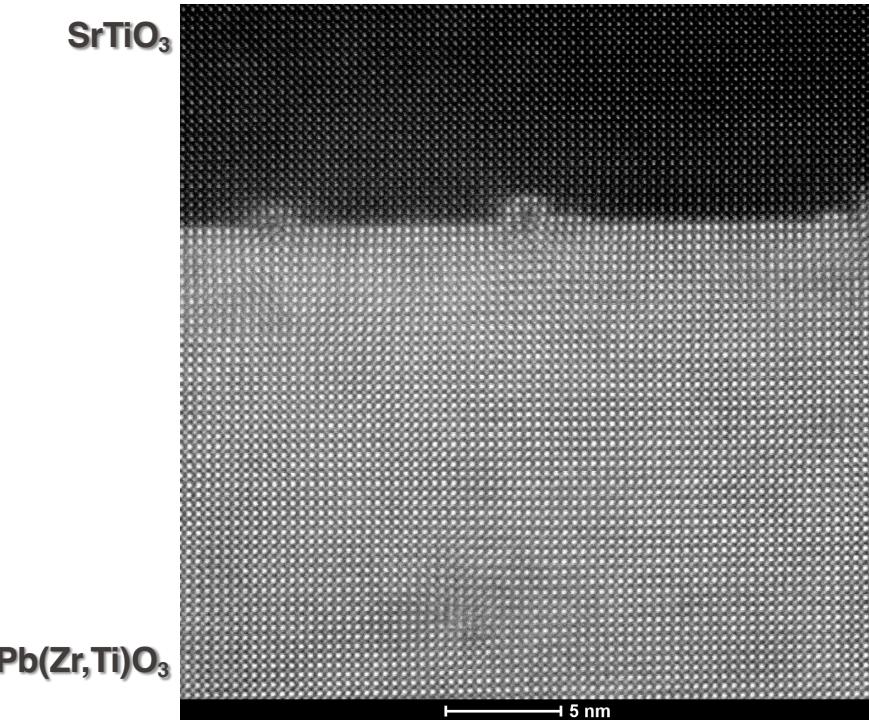
HCP inclusion and dislocation

Atomic scale symmetry and polar nanoclusters in the paraelectric phase of ferroelectric materials



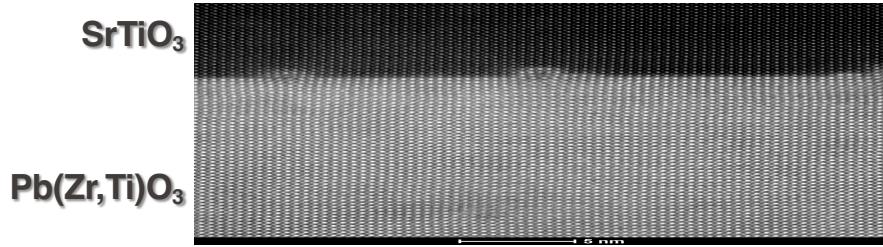
Cs-correction: probe-corrected HR-STEM

Cs-corrected atomic resolution HAADF-STEM of perovskite interface (300 kV)



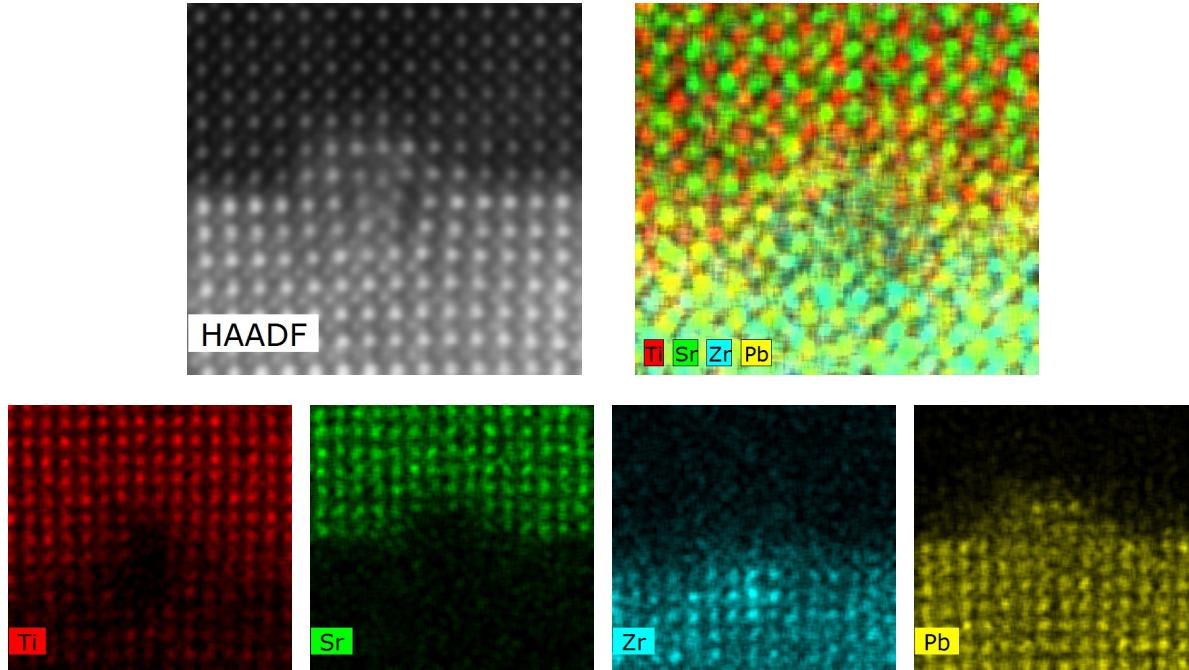
Cs-correction: probe-corrected HR-STEM

Cs-corrected atomic resolution HAADF-STEM of perovskite interface (300 kV)

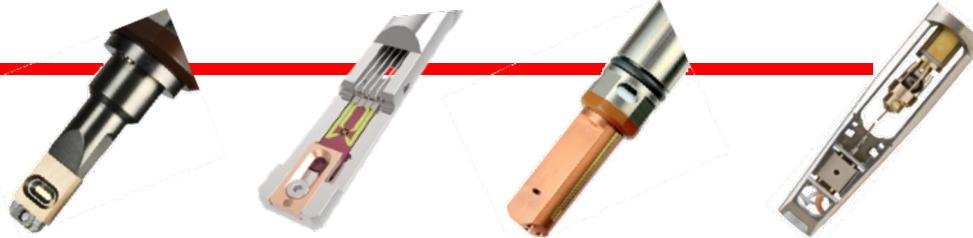


Cs-correction: probe-corrected HR-STEM

Atomic resolution STEM-EDX mapping reveals diffusion of Pb into strained region of misfit edge dislocation



Stimuli	Possible techniques	Information
<ul style="list-style-type: none">• gas• liquid• temperature• magnetic field• current/voltage• mechanical load• light• ...	<ul style="list-style-type: none">• (S)TEM imaging• diffraction• electron energy-loss spectroscopy• energy-filtered TEM• energy-dispersive X-ray spectroscopy• Lorentz microscopy• holography• ...	<ul style="list-style-type: none">• microstructure• crystallography• chemistry• diffusion/migration• optical properties• electric fields• magnetic fields• ...



Different dedicated holders

Liquid phase processes

Hydration and other liquid phenomena
Crystal growth from the liquid phase
Corrosion

Phase transformations

Solid state phase transformations
Crystallization and melting
Structural transformations
Solid state reactions
Solid state transformations in nanostructured materials
Size-dependent transformations in embedded nanoparticles
Shape and phase transformations in free-standing nanoparticles
Sintering of nanoparticles

Elastic and plastic deformation

Microscopic phenomena during plastic deformation
Deformation of polycrystalline materials
The effect of gas environment on deformation
Grain boundary motion
Deformation phenomena in single crystals
Deformation of multilayers
Relaxation of epitaxially strained materials
Mechanical properties of nanostructures, thin films and surfaces
In situ indentation and straining of thin films
Mechanical properties of nanostructures
Surfaces: Tribology and Nanomanipulation

Surface reactions and crystal growth

Modification of surface structure
Oxidation and other chemical reactions at surfaces
Growth of nanostructures
Carbon nanotubes
Thin film growth and defect formation
Epitaxial growth
Polycrystalline growth
Crystal growth on patterned substrates

Domain wall motion and flux dynamics

Magnetic domain switching
Flux motion in superconductors
Switching phenomena in ferroelectrics

Correlation of structural and electronic properties of materials

Electrical measurements on TEM samples: samples as devices
Electrical measurements on individual nanostructures

Beam induced processes

Electron beam induced phenomena
Interaction with the vapour above the specimen
Formation of point defects
Beam induced transformations, surface reactions, growth
Radiation enhanced dislocation motion
Hole drilling
Ion implantation
High energy ion accelerators
FIB in the TEM

- A window into the behavior of materials under real processing conditions.
- A continuous view of a process, which may take the place of multiple post-mortem measurements.
 - It is easier to catch a transient phase or observe a nucleation event.
 - Specific and detailed kinetic information, such as the motion of individual dislocations under known stress, or growth rates of individual nanocrystals.
- This unique information comes at the cost of increased experimental complexity.
- **Expensive: machine time, holders**

TEM is now not one technique that can be easily summarised, but is split into many specialisms. In essence this is due to the many types of interaction of the electron beam with the atoms of a sample.

Modern TEM instruments are arguably the most versatile analytical tools. Many other possible uses (e.g. imaging of magnetic domains, optical plasmon mapping, in-situ studies) exist..

Aberration-correction and improved instrument stability give sub-Å resolution in TEM and STEM. With lower beam voltages lighter elements can be analysed without beam damage.

Faster, more sensitive spectrometers give unprecedented access to composition, chemistry and physics of materials.

Computer interfaces and software allow acquisition and processing of large datasets.

With the latest instrumentation, the sample and specimen preparation are often the limiting factor!

Some useful literature

Transmission Electron Microscopy by D.B. Williams and C.B. Carter (Springer)

Large Angle Convergent Beam Electron Diffraction by J.P. Morniroli

Aberration-corrected imaging in transmission electron microscopy: an introduction by R. Erni

Scanning Transmission Electron Microscopy by S.J. Pennycook and P.D. Nellist (eds) (Springer)

Diffraction Physics by J.M. Cowley (North Holland/Elsevier)

Science of Microscopy by C.W. Hawkes and J.C.H. Spence (eds) (Springer)

Transmission Electron Microscopy: Physics of Image Formation and Microanalysis by L. Reimer